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ACER

JM31/SJM31/BAP31

Discrete

MAIN BOARD

2009.05.26

Tuesday, May 26, 2009		A03
DATE	CHANGE NO.	REV

	EE	DATE	POWER	DATE	INVENTEC			
DRAWER					TITLE BAP31G SFF			
DESIGN								
CHECK								
RESPONSIBLE								
SIZE=				VER:	SIZE	CODE	DOC NUMBER	
FILE NAME: 00000000000000000000					C	CS	D-CS-1310A2264501-ALG	REV
P/N	000000000000				SHEET	1	of	47

1. Schematic Page Description :
Montevina Schematic Ver : A03

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1. Title

2. Schematic Page DESCR

3. Block Diagram

4. Annotations

5. Schematic Modify

6. Timing Diagram

7. Power Block Diagram

8. Adaptor in/Charge

9. 5VLA/5VA/3VA

10. 3VS/5VS/1.5V (DDR3)

11. 1.05VS/1.5S/1.8V/1.5VA

12. Power Latch/1.5VS/SCREW HOLE

13. CPU Core Power

14. GPU Core Power

15. Penryn Processor(1/2)

16. Penryn Processor(2/2)

17. CPU Thermal

18. Cantiga Host(1/6)

19. Cantiga DMI/Graph(2/6)

20. Cantiga DDRII(3/6)

21. Cantiga Power(4/6)

22. Cantiga Power(5/6)

23. Cantiga Ground(6/6)

24. Clock Generator

25. DDR3 SDRAM SO-DIMM0

26. DDR3 SDRAM SO-DIMM1

27. ICH9M CPU/IDE/SATA(1/4)

28. ICH9M PCI/PCIE/DMI/USB(2/4)

29. ICH9M GPIO(3/4)

30. ICH9M Power/GND(4/4)

31. LCD CNN/SATA/3G/WLAN

32. KBC ITE8512F

33. IO CN

34. IO CN

35. IO CN

36. Audio Codec

37. BLANK

38. M92-S2(1/5)

39. M92-S2(2/5)

40. M92-S2(3/5)

41. M92-S2(4/5)

42. M92-S2(5/5)

43. DDR3 VRAM

44. HyBrid Switch

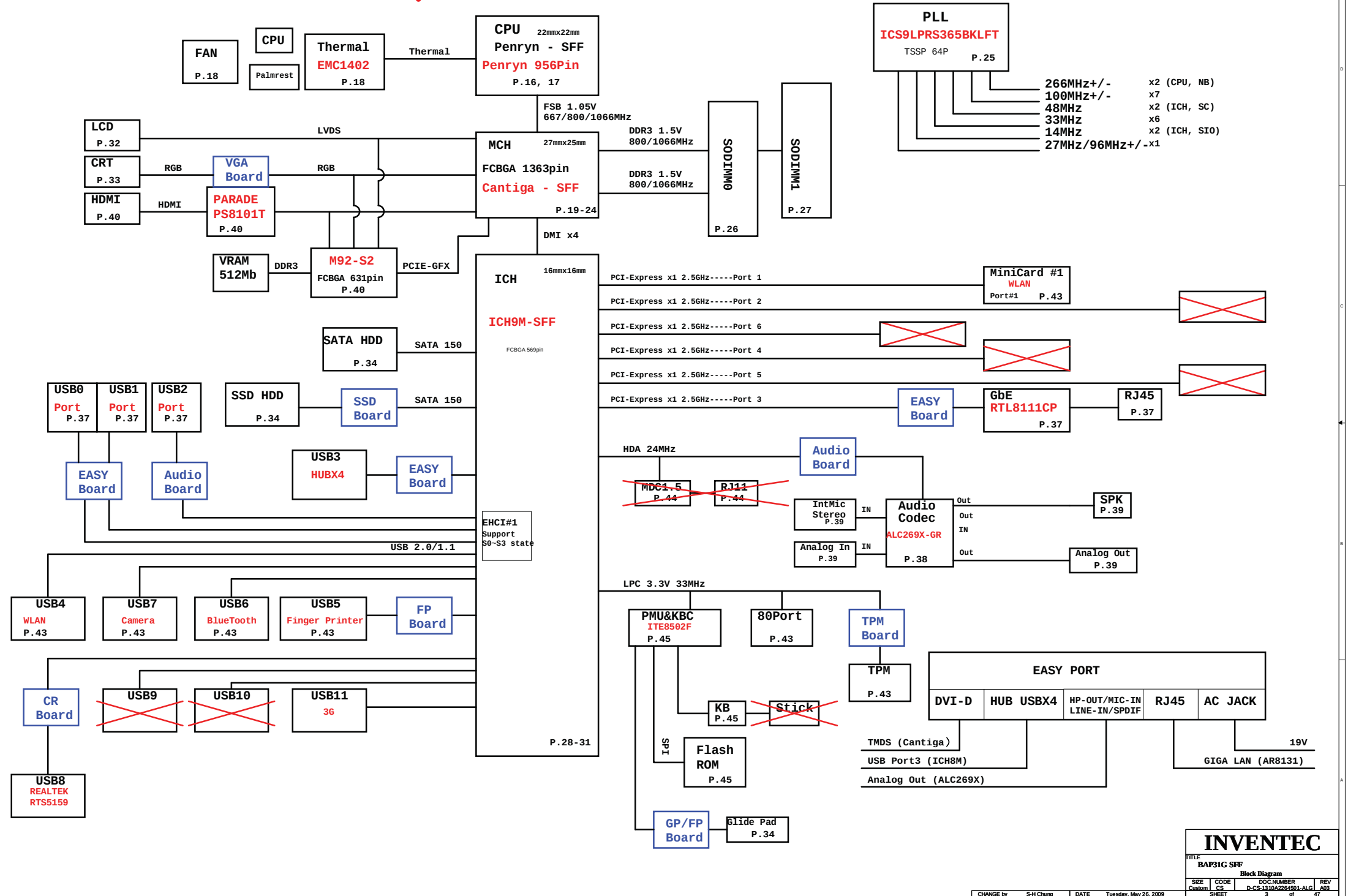
45. dGPU Power

46. dGPU Power

47. dGPU Power

3. Block Diagram

<http://hobi-elektronika.net>



4. Net name Description

Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R
VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI/PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R
+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

Part Naming Conventions

C	=	Capacitor
CN	=	Connector
D	=	Diode
F	=	Fuse
L	=	Inductor
Q	=	Transistor
R	=	Resistor
RP	=	Resistor Pack
U	=	Arbitrary Logic Device
Y	=	Crystal and Osc

Net Name Suffix

#	=	Active Low signal
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5. Board Stack up Description

PCB Layers

Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

		Voltage	S0 Current
		1.3319V~1.4375V~1.4591V	18A
		0.9221V~0.9625V~0.9739V	
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+HIMEL+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V~1.05V~1.10V 0.997V~1.05V~1.102V 0.9975V~1.05V~1.1025V 0.9975V~1.05V~1.1025V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V 0.997V~1.05V~1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.71V~1.8V~1.89V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V 1.425V~1.5V~1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA 650mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V~1.5V~1.575V	3.1A(800M) 4.1A(1067M)
0.75VDDT_DDRIII	DDRIII Terminator:	0.7125V~0.75V~0.7875V	1.0A
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TV DAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLF Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V~3.3V~3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.135V~3.3V~3.465V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V 3.0V~3.3V~3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA ODD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V~3.3V~3.6V 3.0V~3.3V~3.6V 4.75V~5.0V~5.25V 4.75V~5.0V~5.25V 4.75V~5.0V~5.25V 4.75V~5.0V~5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	5VA 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V~3.3V~3.6V	300mA

INVENTEC			
BAP31G SFF			
ANNOTATIONS			
SIZE	CODE	DOC NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET 4 of 47			

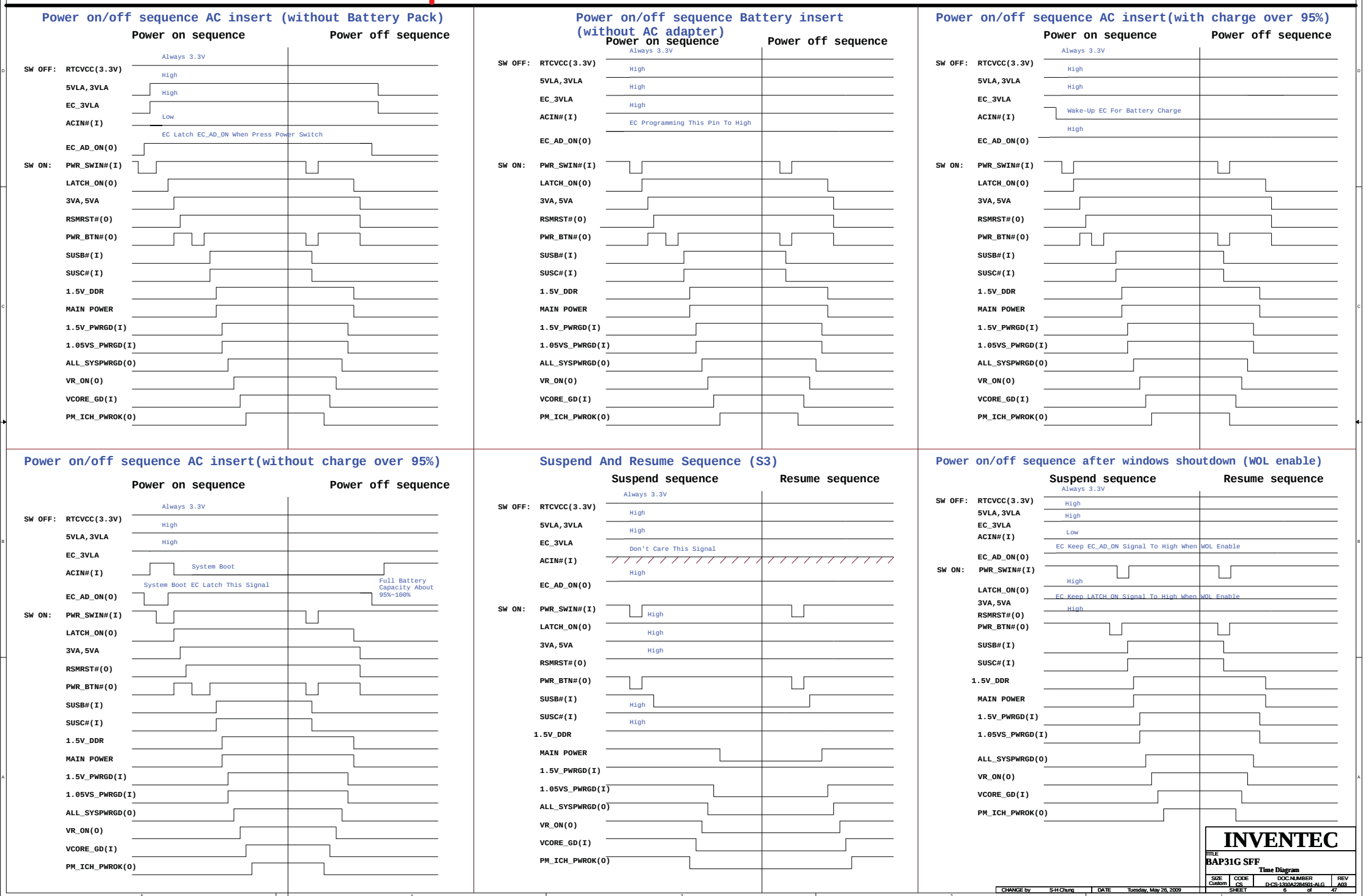
6.Schematic modify Item and History

- 2009.0108
1. ADD USB P3 for Docking, USB P5 for Finger printer,
Modify CN5 -----P28

2. Modify CN20 to 50pin-----P33

3. Move PWR_SWIN# from CN14 to CN20

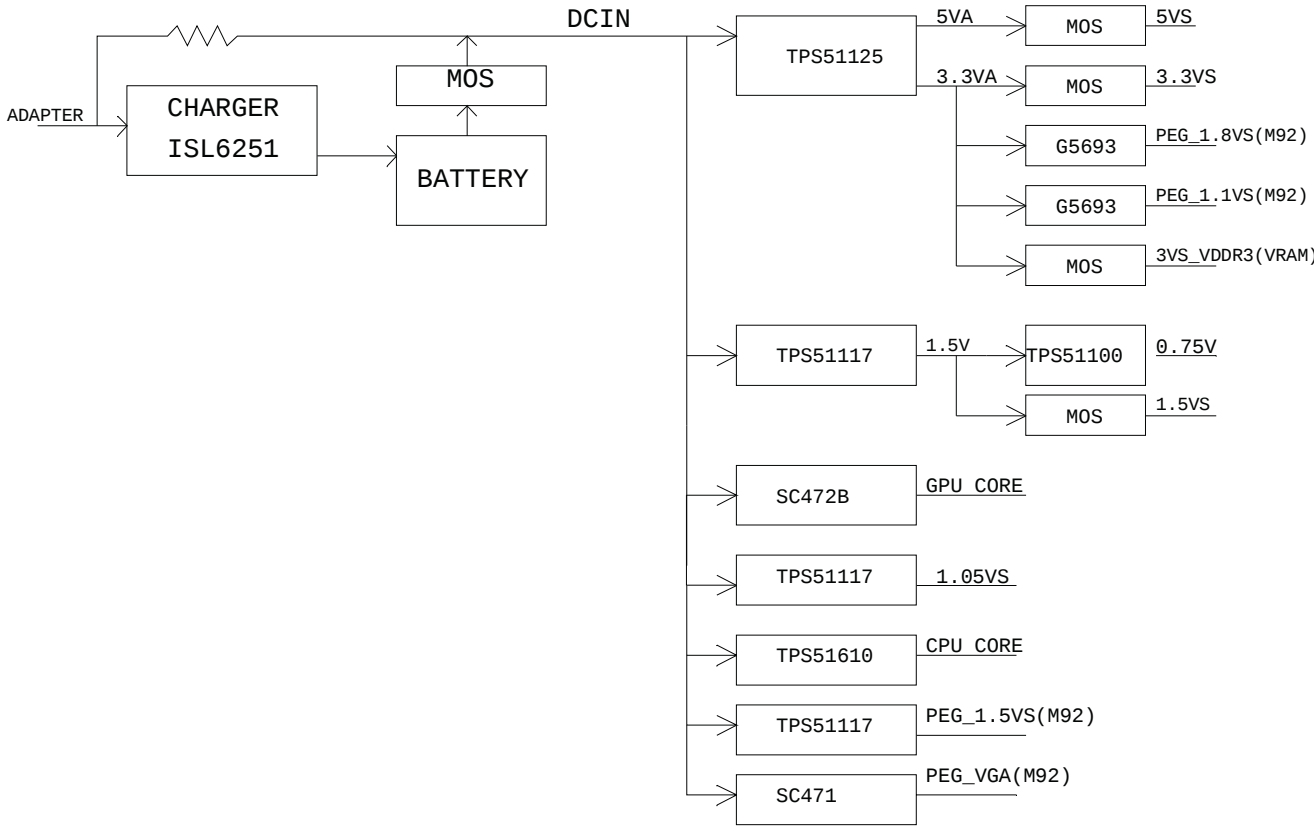
4. ADD TPM module-----P34
- 2009.0109
1. ADD DOCK_USB_EN, DOCK_CRT_IN#-----P32,33
- 2009.0112
1. Change power item: R490,R291,BAT CNN TH PIN



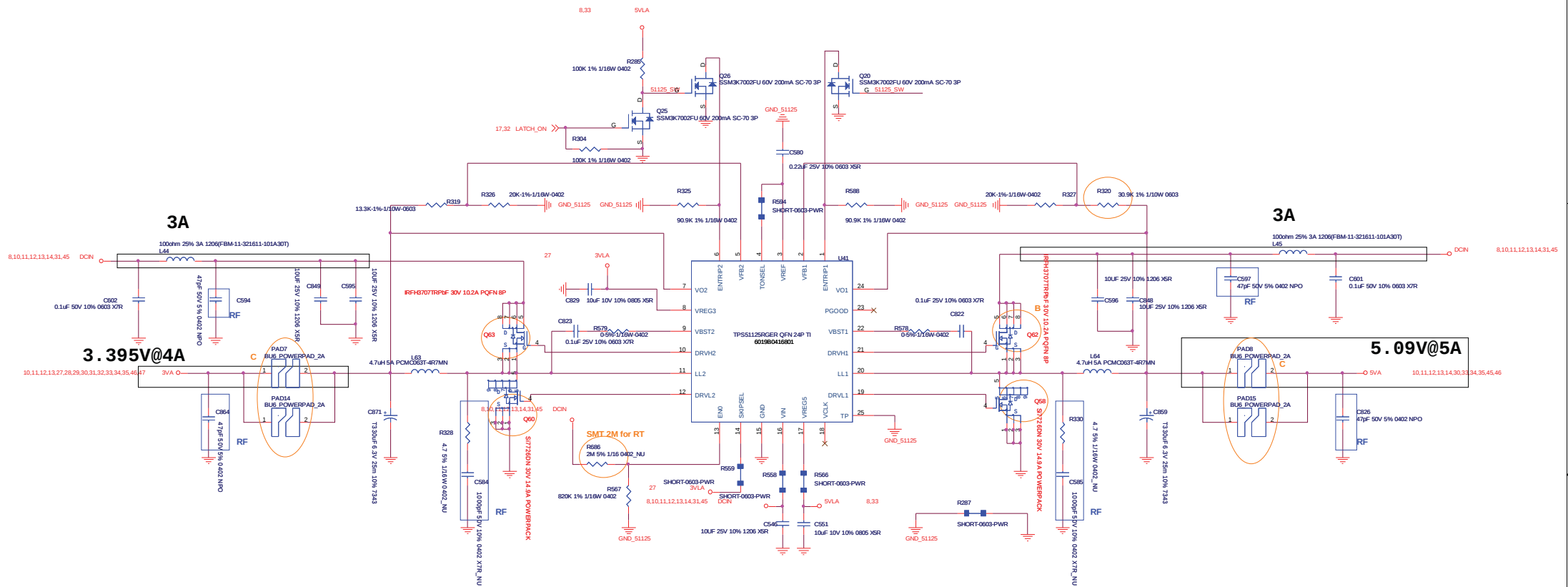
Power Block Diagram

<http://hobi-elektronika.net>

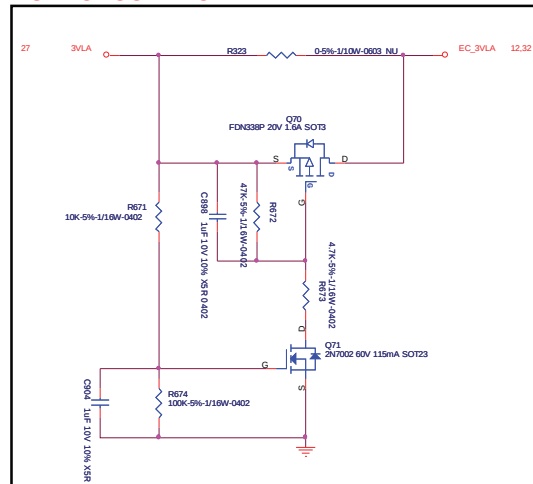
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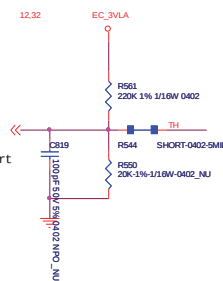
For Green PC



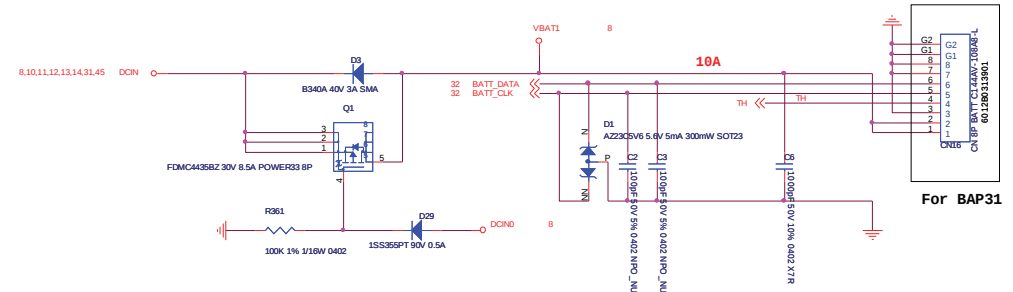
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H: no battery
L: battery insert

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JM31, SJM31 USE 6012B0311301 H=4.7
BAP31 USE 6012B0313901 H=5.25



For BAP31

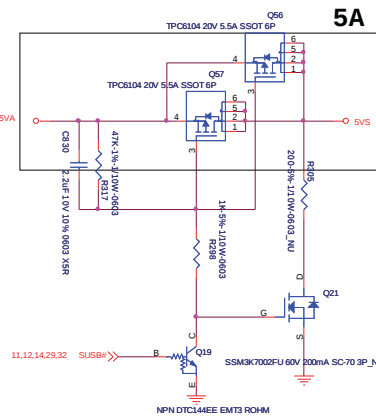
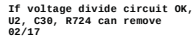
INVENTEC

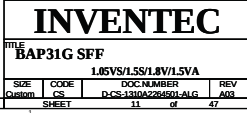
FILE	BAP31G SFF
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5VI-A/5VA/3VI-A/3VA

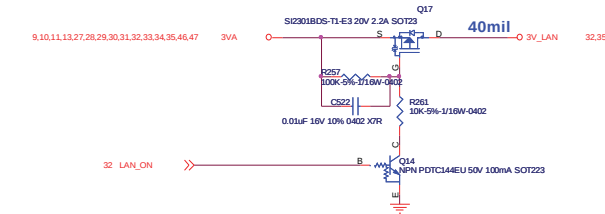
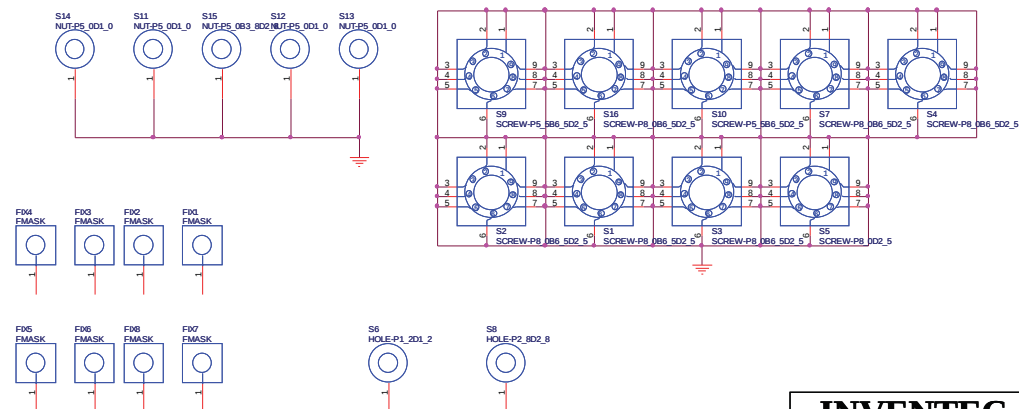
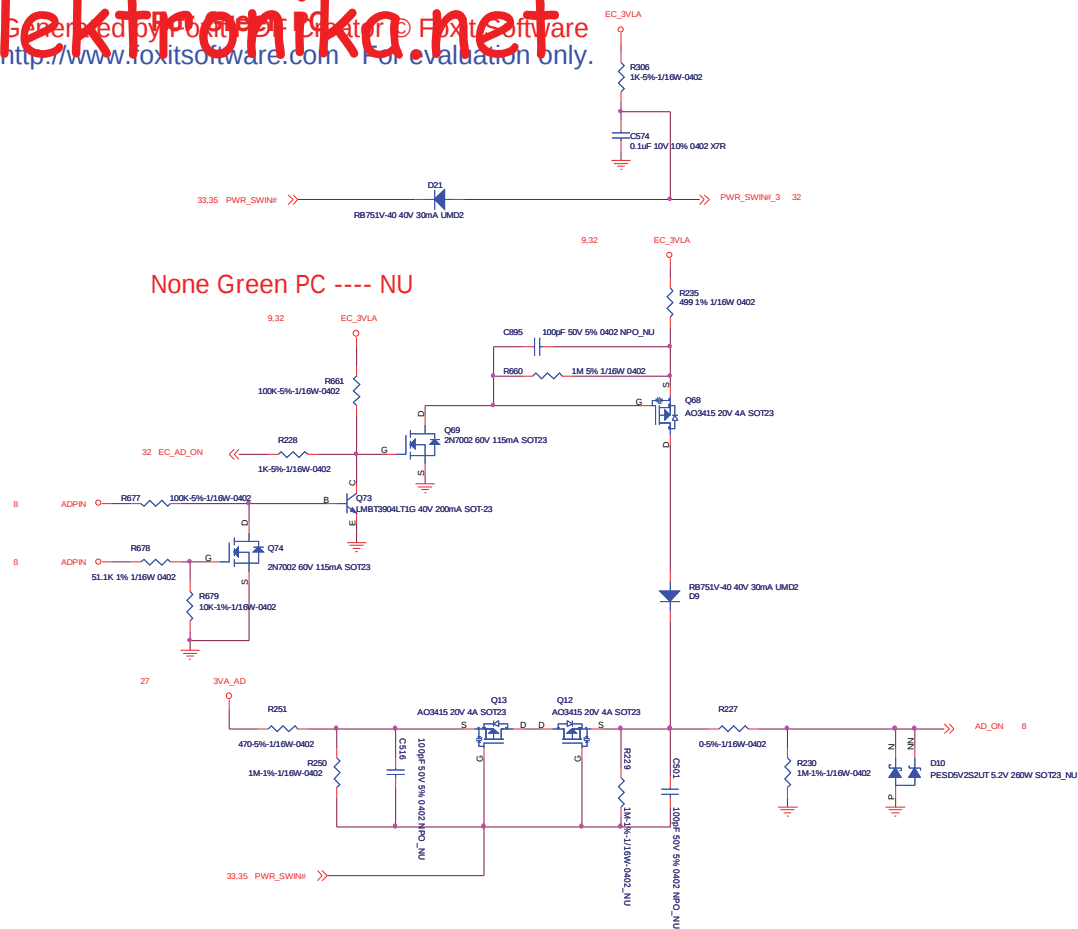
CHANGE by	S-H Chung	DATE	Tuesday, May 26, 2009
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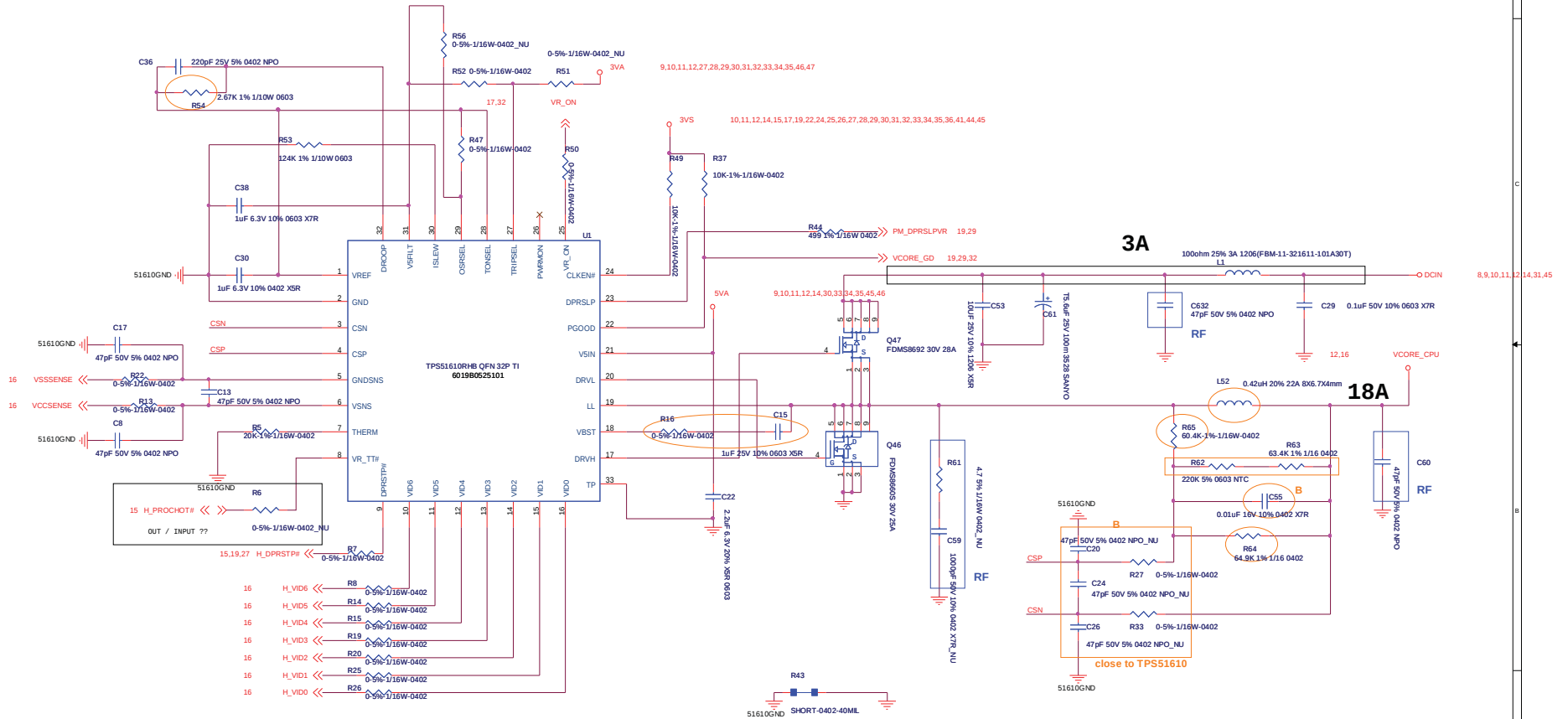
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SHEET		9 of	47



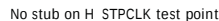


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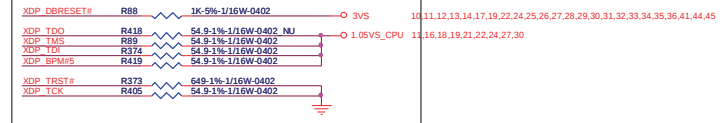
[illegible]







— Should be connect to ICH9 and Cantiga without T-ing(no stub



A#[32-39], APM#[0-1]:Leave escape routing on for future functionality



Zo=55ohm, 0.5" max for GTLREF, Space any other switch signals away from GTLREF with a minimum of 25mils.

Don't allow the GTLREF routing to create splits or discontinuities in the reference planes of the FSB signals

H_PWRGD rise time :
Max : 15ns

Comp0,2 connect with $Z_0=27.4\Omega$, make trace length shorter than 0.5" and width is 18mils.
Comp1,3 connect with $Z_0=55\Omega$, make trace length shorter than 0.5" and width is 5mils



ULV Dual-Core : 18A(max)
ULV Single-Core : 9A(max)

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Steady-state current : 2.5A (max)

Place these inside socket cavity on L8
(North side secondary)

Place these inside socket cavity on L8
(South side secondary)

Place these inside socket cavity on L1
(North side Primary)

Place these inside socket cavity on L1
(South side Primary)

North side secondary

South side secondary

11.15,18,19,21,22,24,27,30 1.05VS_CPU

160mil

Intel item 6

Place these inside socket cavity on L8
(North side secondary)

138mA (max)

Close to CPU
pin B34

Impedance 55 Ohm, W:S= 1:2

Mismatch 25mil

18mil
7mil space
25mil space with other

Route VCCSENSE and VSSSENSE traces
at 27.4 ohms. Place PU and PD within
2 inch of CPU

CPU Penryn_SFF FCBGA 956P INTEL
6025B0091.002

INVENTEC

BAP31G SFF

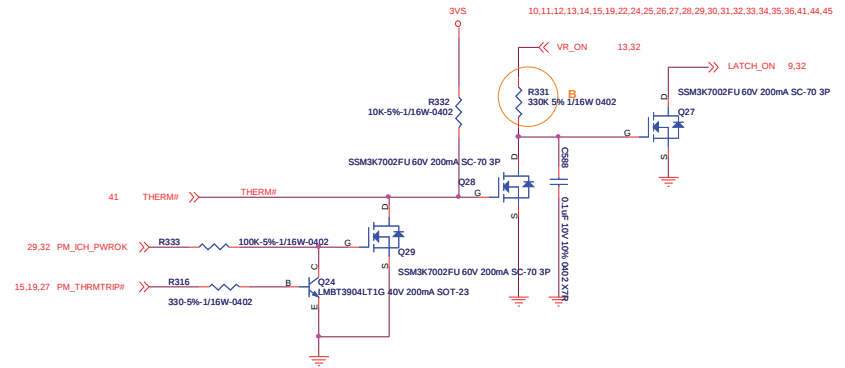
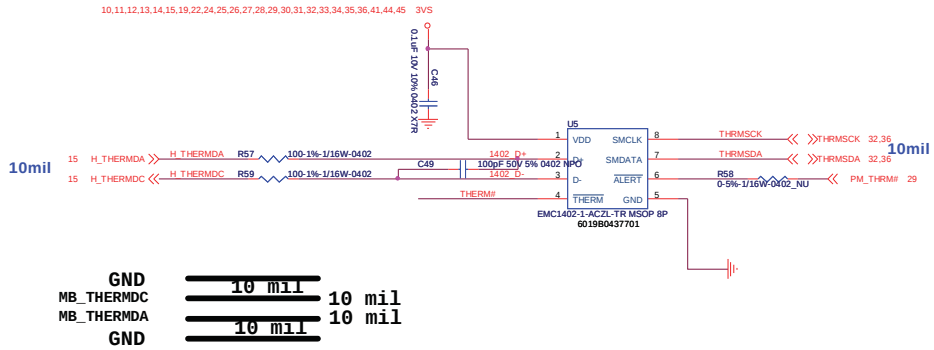
Penryn Processor(2/2)

SIZE CODE DOC NUMBER
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SHEET 16 of 47

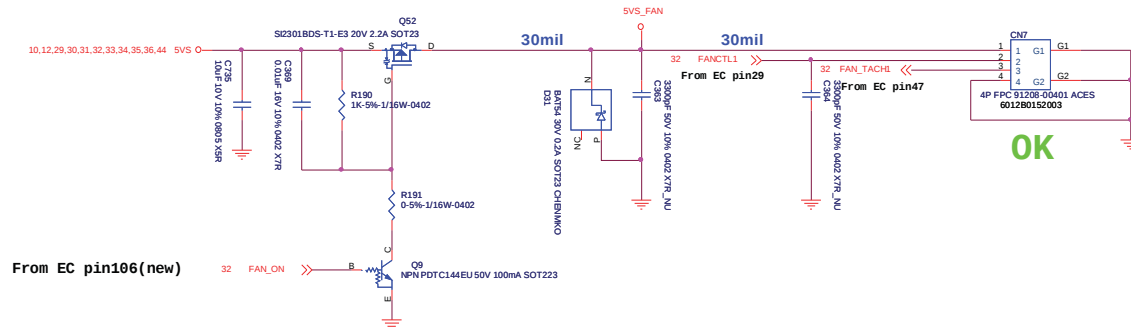
CHANGE by S-H Chung

DATE Tuesday, May 26, 2009

THERMAL SENSOR



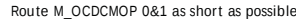
Fan control

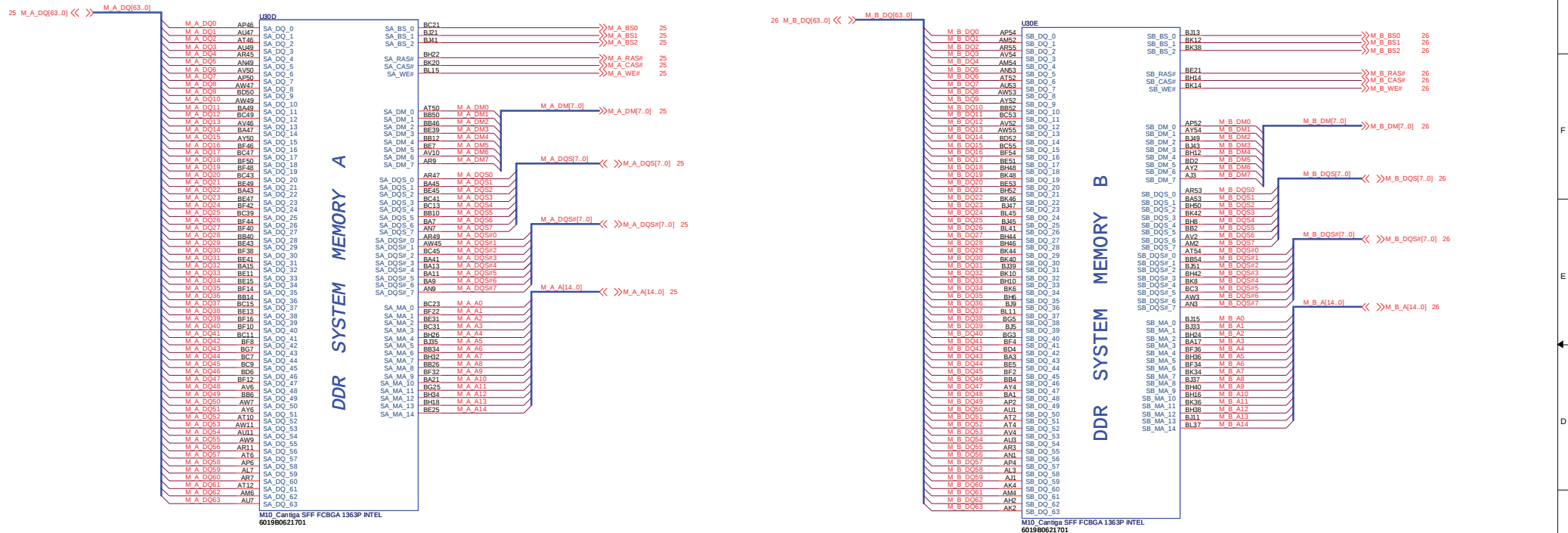


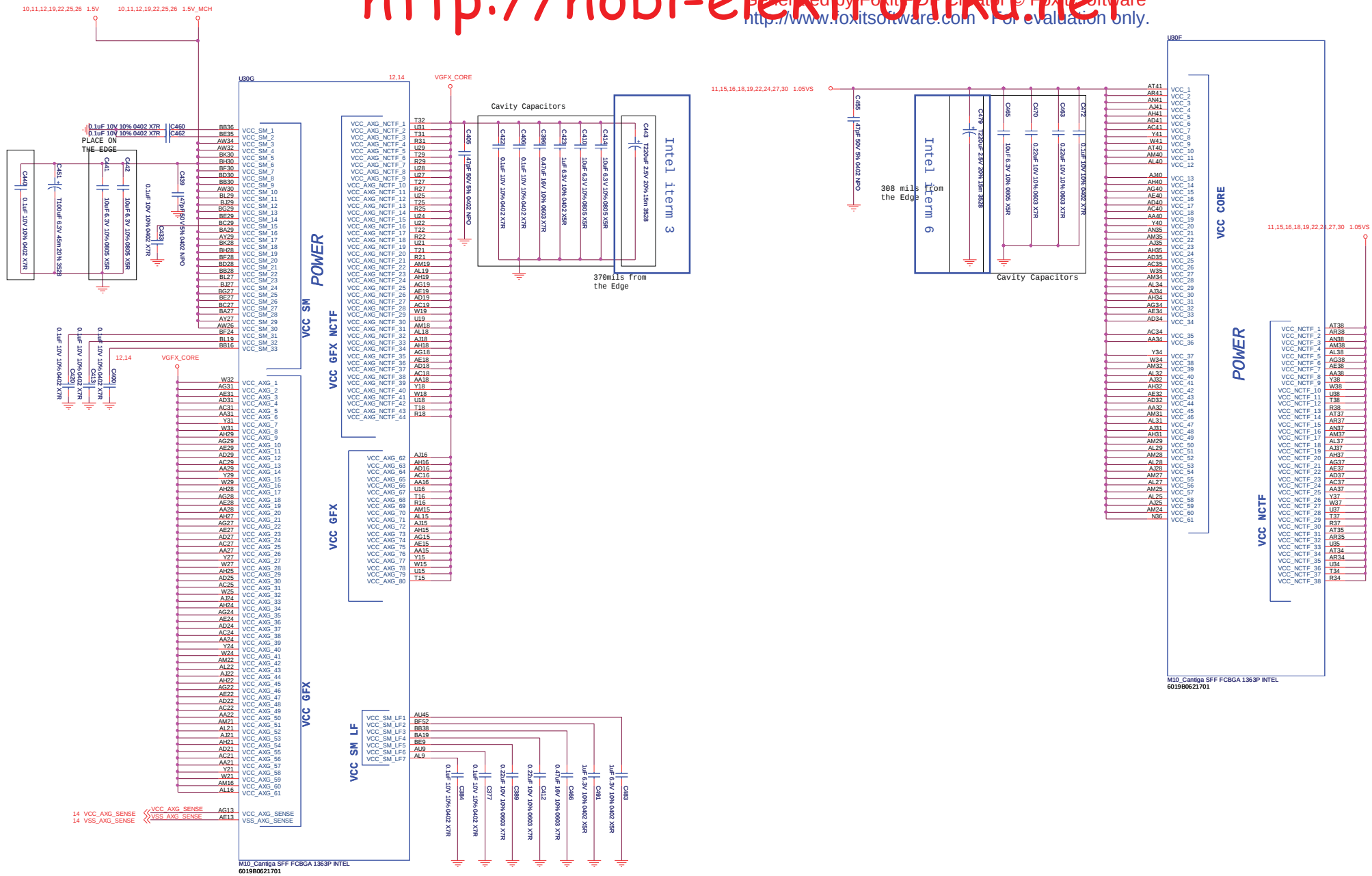
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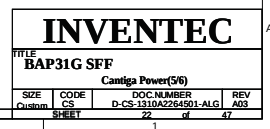
INVENTEC			
TITLE BAP31G SFF			
CPU Thermal			
SIZE Custom	CODE CS	DOC. NUMBER D-CS-13.10A2264501-ALG	REV A03
SHEET		17	of 47





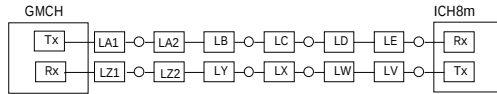
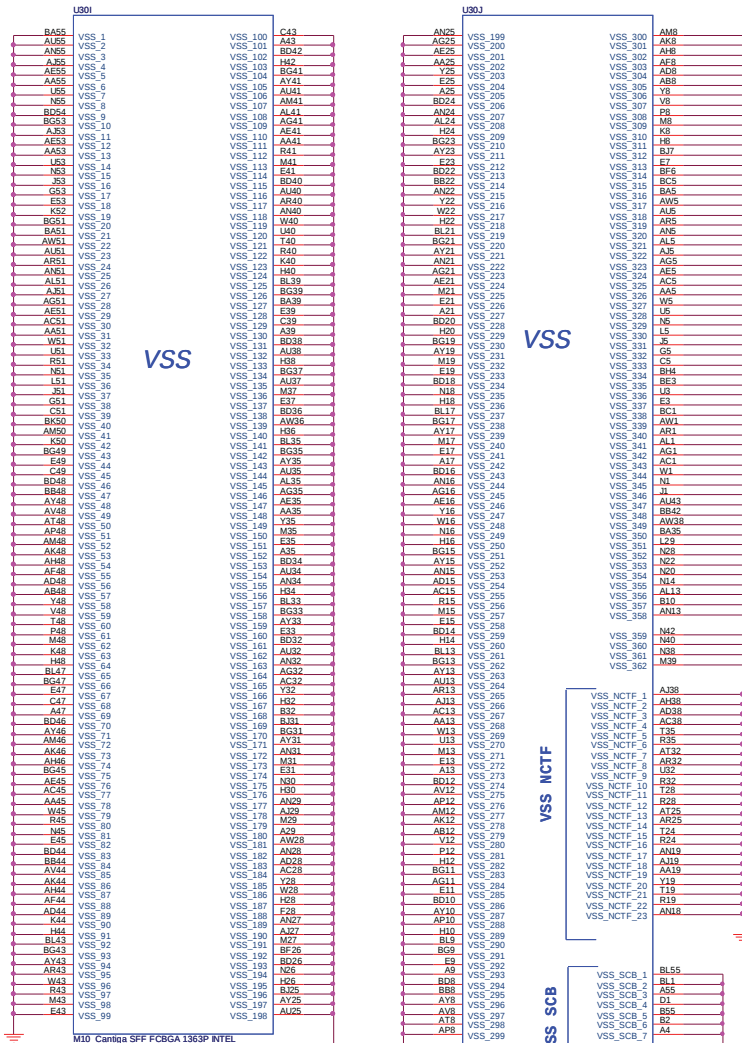






DMI Routing Guideline

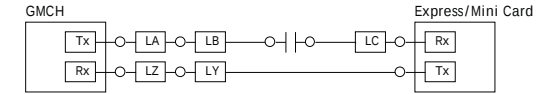
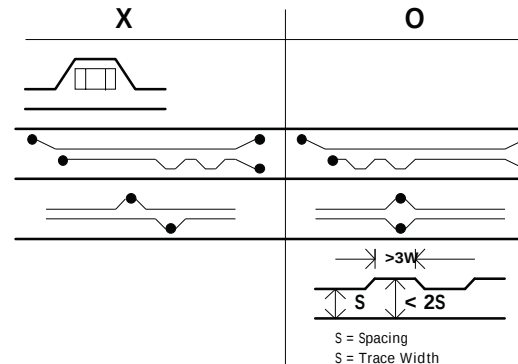
PCIE Routing Guideline



Breakout/in LA/LZ	Main Route LB/LV	Breakout/in LE/LV	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Differential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (GMCH Breakout)	Max = 250 mils	
Trace Length-LB (GMCH Breakout to Via2)	Max = 3600 mils	
Trace Length-LC (Via2 to Via3)	Max = 5900 mils	
Trace Length-LD (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LE (ICH7m Breakout)	Max = 400 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICH7m Breakout)	Max = 400 mils	
Trace Length-LW (ICH7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to GMCH Breakout)	Max = 3600 mils	
Trace Length-LZ (GMCH Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	

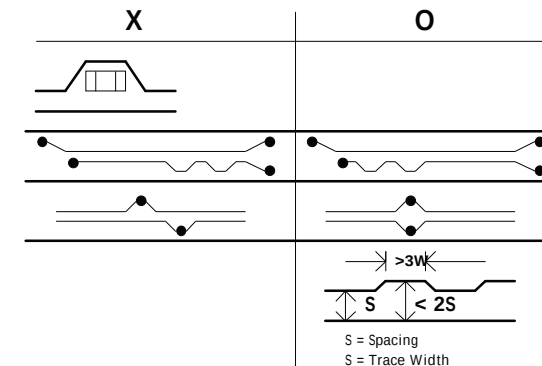
*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
*** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils

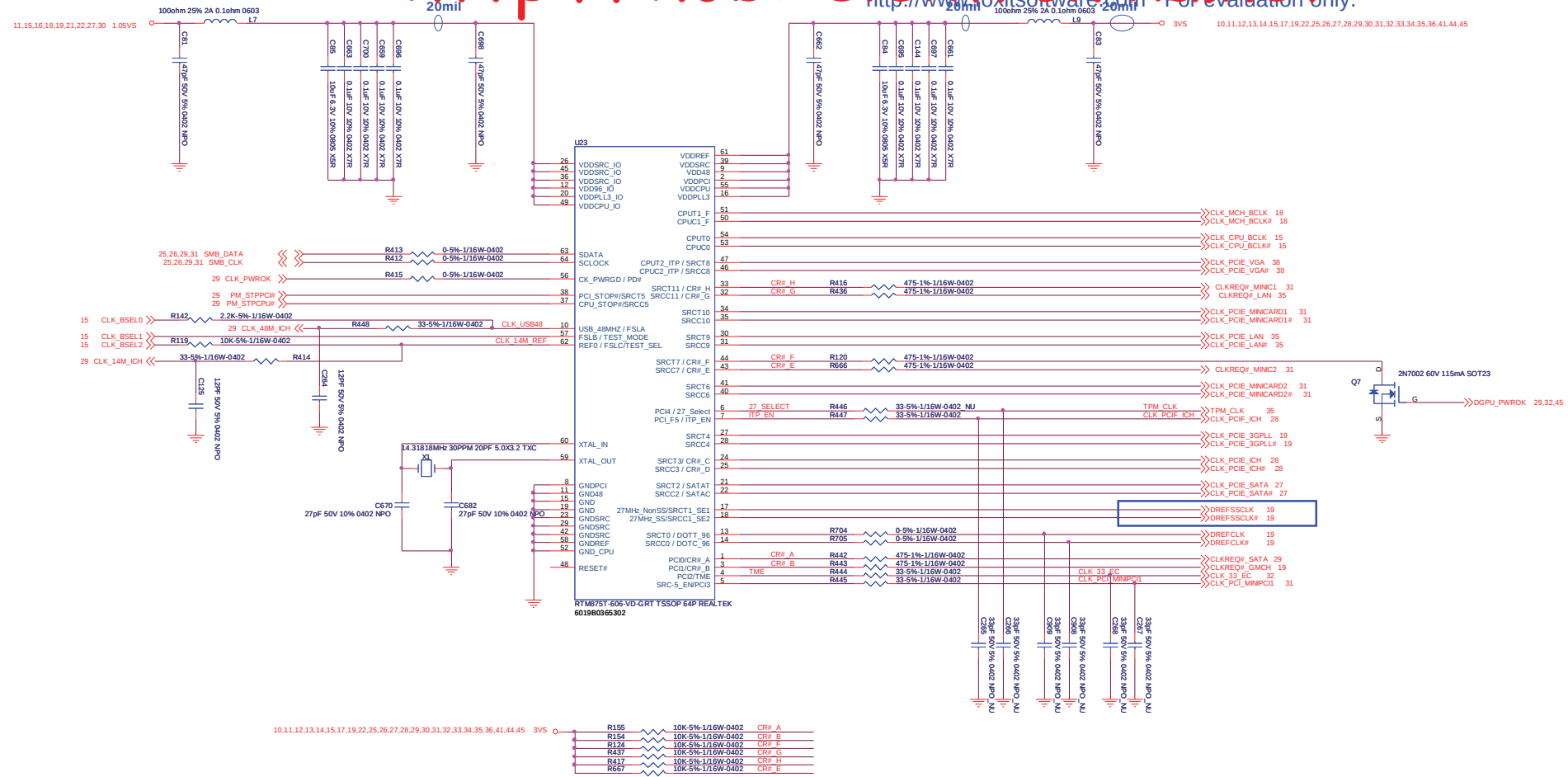


Breakout/in LA/LZ	Main Route LB/LV	Main Route LD/LW	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	
Nominal Differential Trace Space	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 20 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	
Trace Length-LA (ICH7m Breakout)	Max = 400 mils	
Trace Length-LB (ICH7m Breakout to AC cap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils	
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils	
Trace Length-LZ (ICH7m Breakout)	Max = 400 mils	
Trace Length-L2 (LY+LZ)	Max = 12000 mils	

*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
*** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils





FSA	FSB	FSC	FSB CLOCK FREQUENCY	HOST CLOCK FREQUENCY
1	1	0	667	166
0	1	0	800	200
0	0	0	1067	266 *

ITP_EN = 0
SRCB/SRCB#
ITP_EN = 1
ITP/ITP#

27_SELECT = 0
DOT196/ LCD_SS /SE
27_SELECT = 1
SRC0/ 27MHz

146
145
144
143
142
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140
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7
6
5
4
3
2
1
0

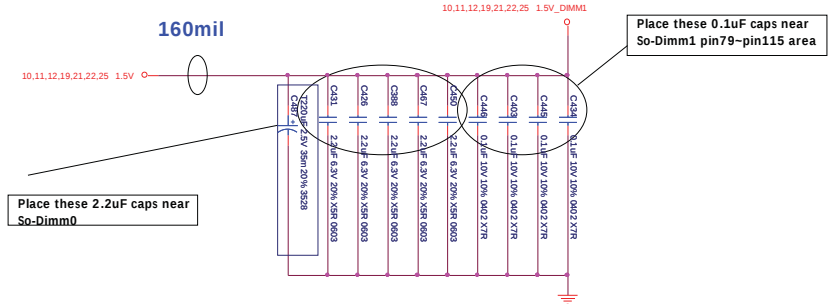
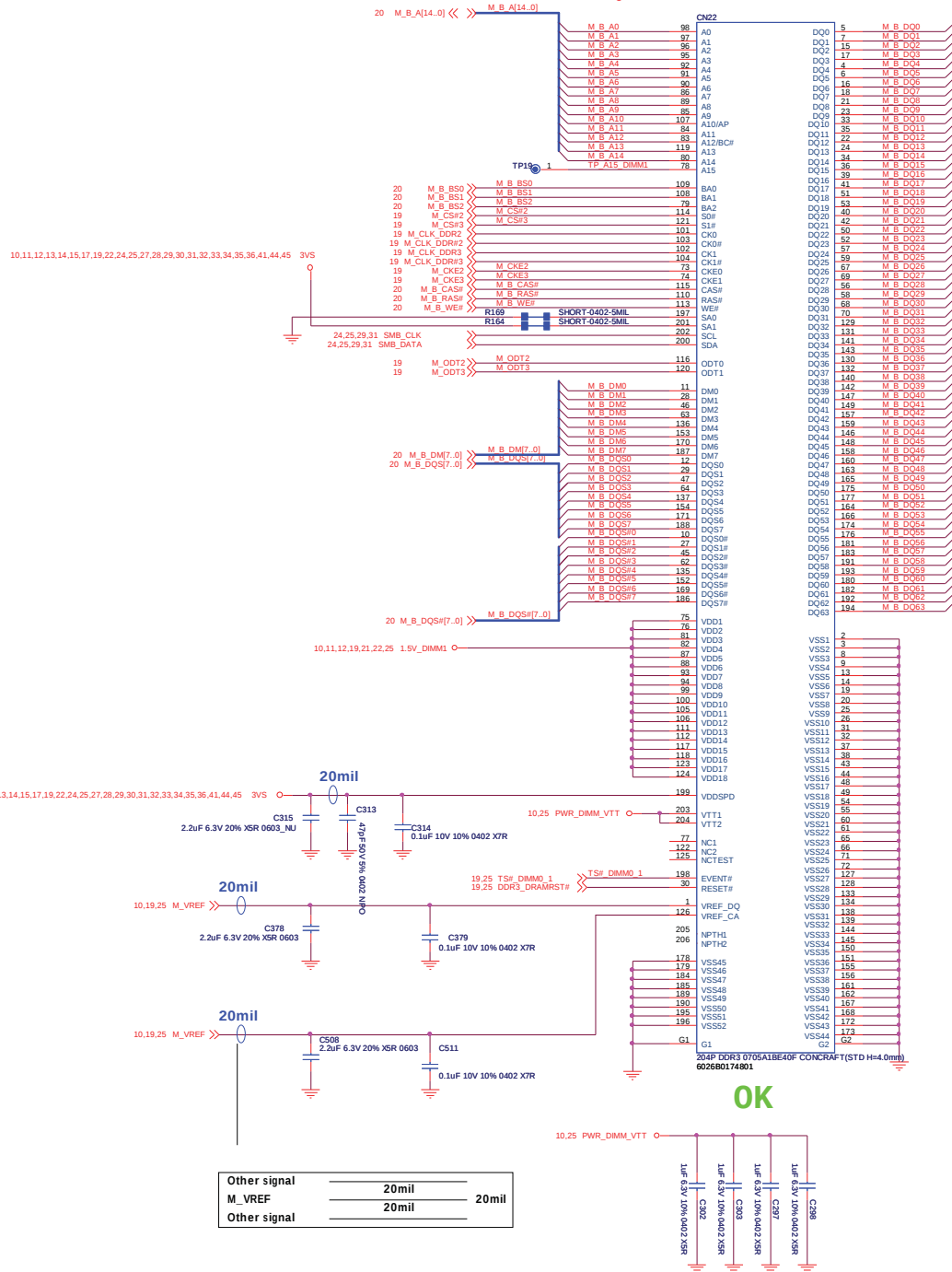
CR#_A:	Byte 5 bit 6=0--->SRC0 bit 6=1--->SRC2	BIT 7=1 (Enable)
CR#_C:	Byte 5 bit 2=0--->SRC0 bit 2=1--->SRC2	BIT 3=1 (Enable)
CR#_B:	Byte 5 bit 4=0--->SRC1 bit 4=1--->SRC4	BIT 5=1 (Enable)
CR#_D:	Byte 5 bit 0=0--->SRC1 bit 0=1--->SRC4	BIT 1=1 (Enable)
CR#_E:	SRC6 (Byte 6)	BIT 7=1 (Enable)
CR#_F:	SRC8 (Byte 6)	BIT 6=1 (Enable)
CR#_G:	SRC9 (Byte 6)	BIT 5=1 (Enable)
CR#_H:	SRC10 (Byte 6)	BIT 4=1 (Enable)

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SO-DIMM1

http://hobi-elektronika.net
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 http://www.foxitsoftware.com For evaluation only.



INVENTEC			
BAP31G SFF			
DDR3 SDRAM SO-DIMM1			
SIZE	CODE	DOC NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG1	A03
SHEET	26	of	47

RTC Circuit

1. RC delay time should be in the range of 18-25ms
2. It is recommended that this larger capacitor and small resistor value in order to reduce the likelihood of glitching of RTCRST#

1. The ICHm requires a length less than 1 inch on each branch (from crystal's terminal to RTCXn ball)
2. Routing the RTC circuit should be kept simple to simplify the trace length measurement and increase accuracy on calculating trace capacitances
3. On FR-4, a 5-mils trace has approximately 2pF per inch
4. Trace signal coupling must be limited as much as possible by avoiding the routing of adjacent PCI signals close to RTCX1 and RTCX2
5. Ground guard plane is highly recommended

For JM31, SJM31

For BAP31

For Green PC

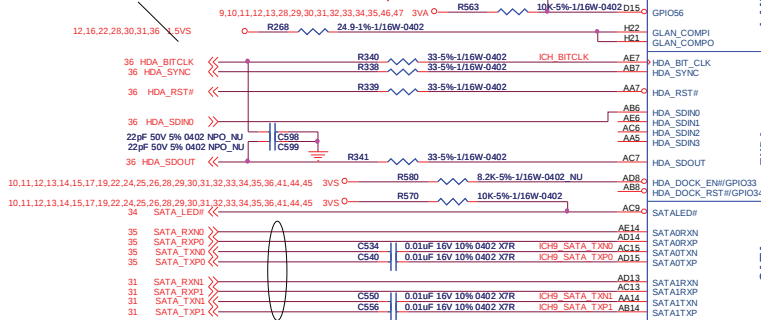


123

CABLE, ROUND, 3POS, 75mm, I, RTC_NU
6027B0066801

RTC Battery Life :
220mAh (220000uAh) / 6uA = 4.2 year

Place all series resistors 0.6 to 2.6 inches from the ICH9



Distance between the ICH9-M and cap on the "P" signal should be identical distance between the ICH9-M and cap on the "N" signal for same pair.

ICH9m internal VR enable strap

	Enable	Disable
INTVRMEN	1(Default)	0

Internal VRM enabled for
VccSus1_05, VccSus1_5,
VccCL1_5, VccLAN1_05 and
VccCL1_05

ACZ_SDATAOUT strap functionality base on RSV09 strap
XOR chain entrance (RSV09 pulled low)
PCIe port config bit 1(RSV09 not pulled low)

Stuff for XOR chain testing

ICH TP3	HDA_SDOOUT	Description
0	0	RSV0
0	1	Enter XOR Chain
1	0	Normal operation (Default)
1	1	Set PCIe port config bit 1

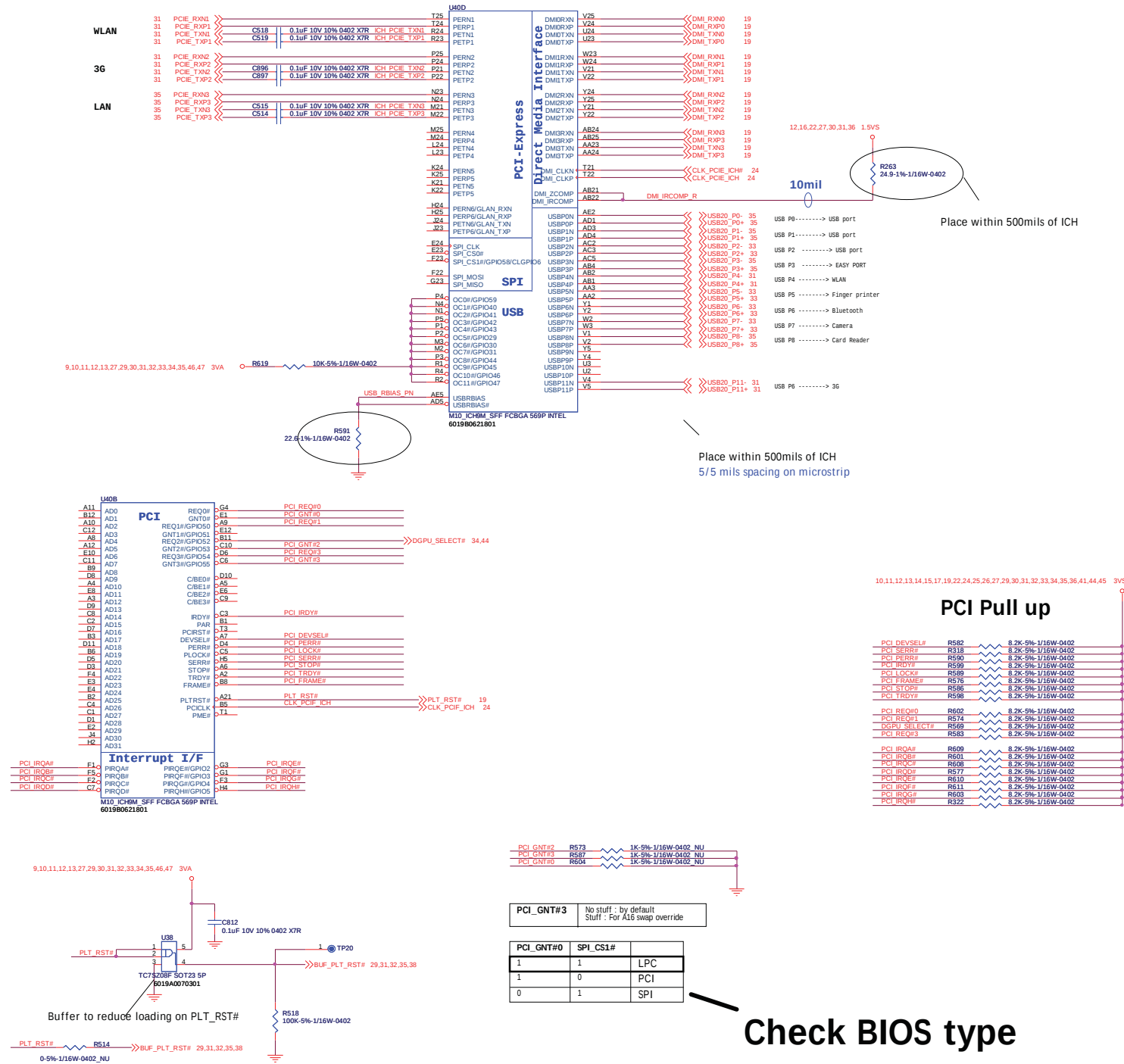
Short pins AG1 and AG2 at the package

By Tony

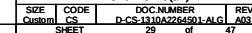
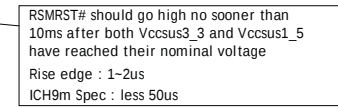
INVENTEC

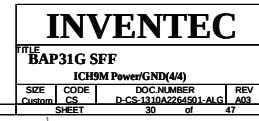
TITLE BAP31G SFF			
ICH9M CPU/IDE/SATA/144			
SIZE Custom	CODE CS	DOC NUMBER D-CS-1310A2264501-ALG	REV A03
SHEET		27	of 47

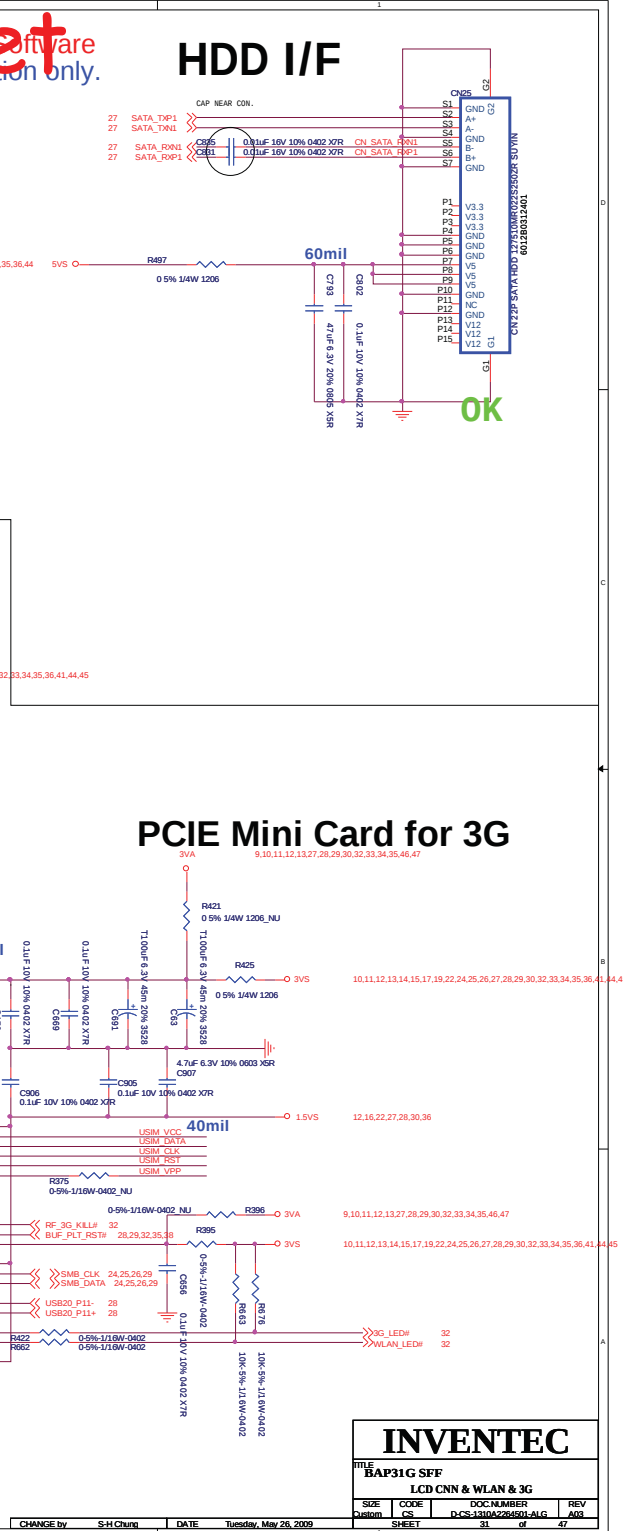
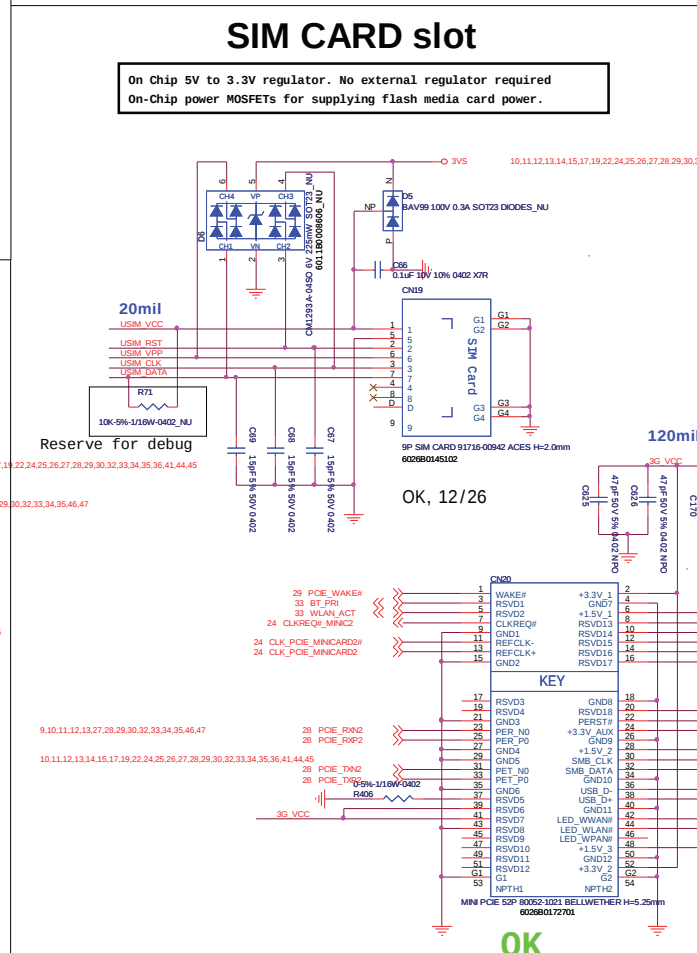
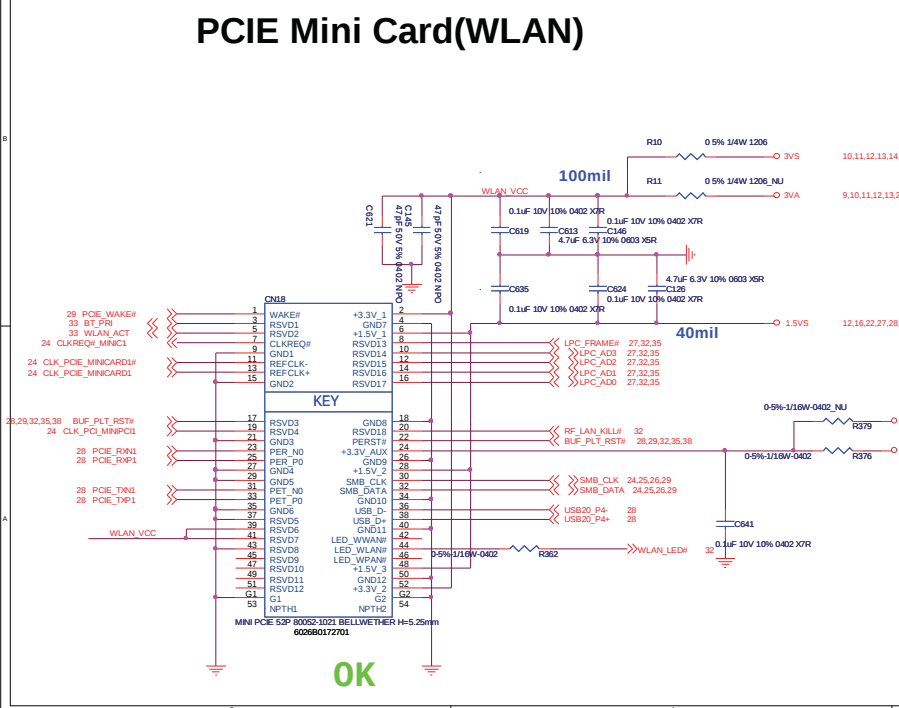
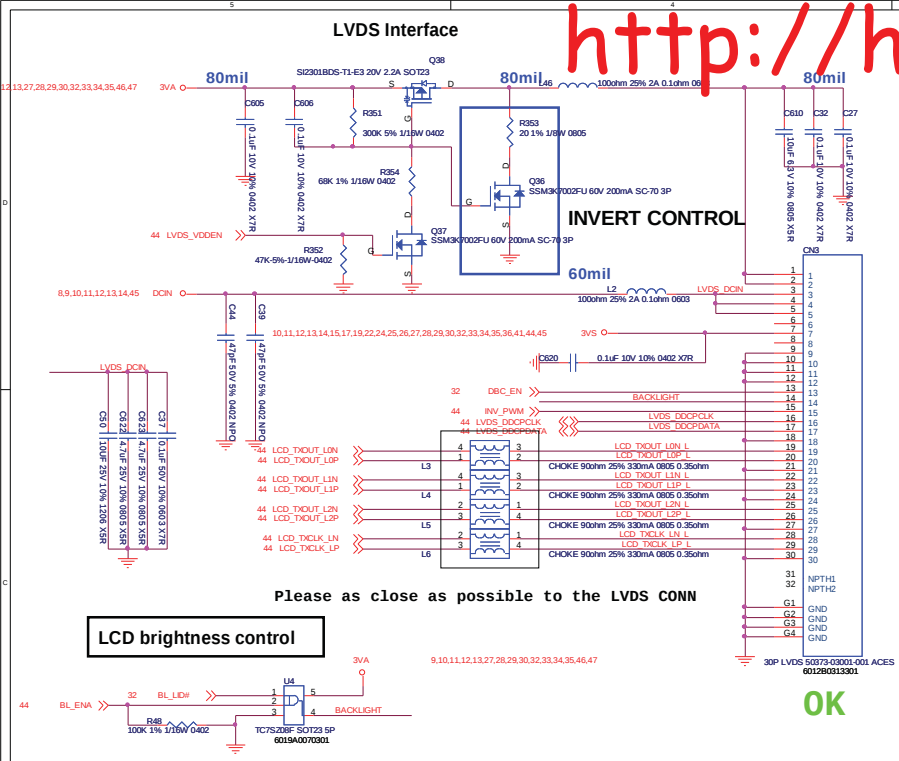
PCIE AC coupling caps need to be within 250mils of the driver

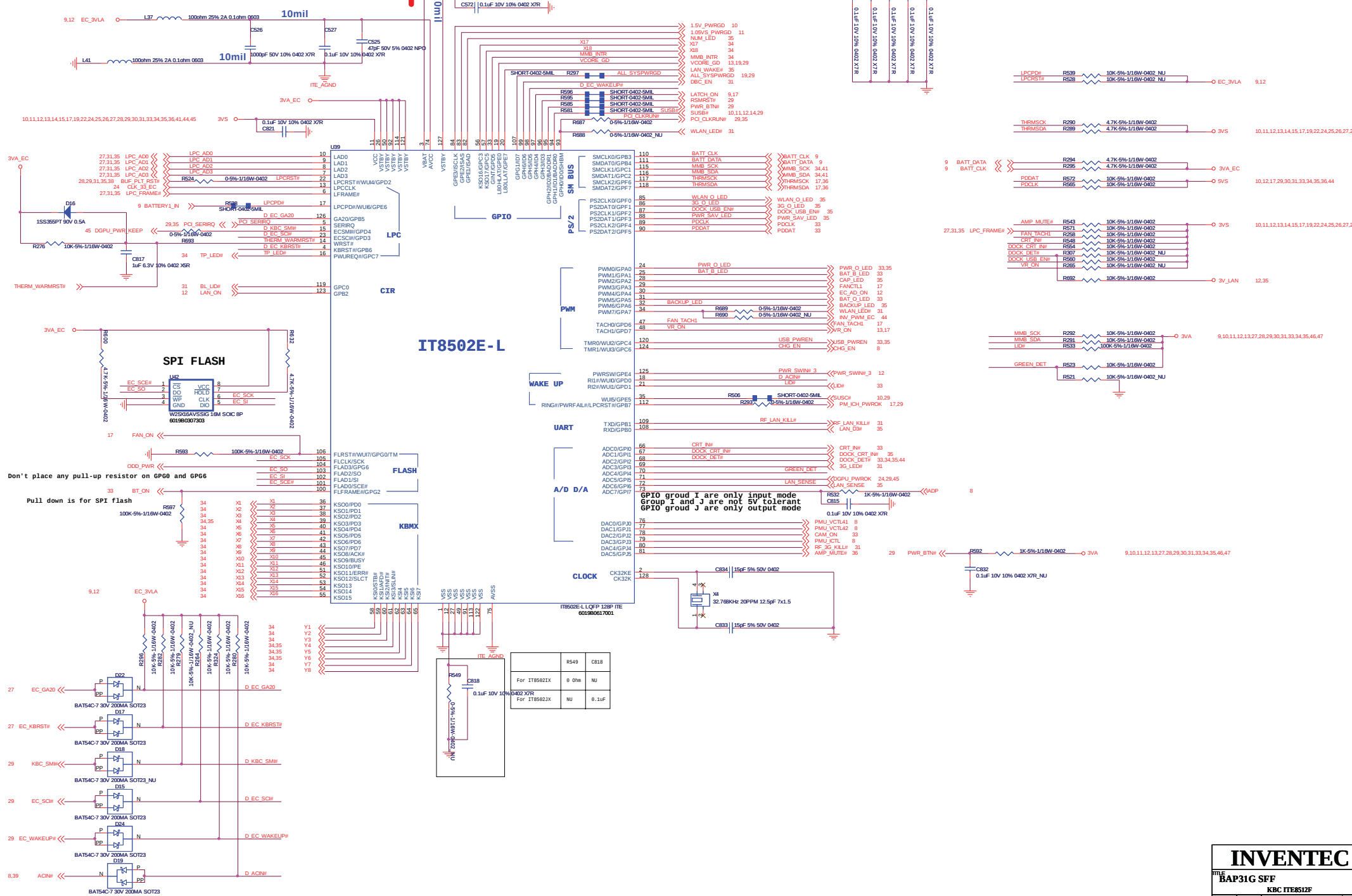


Check BIOS type





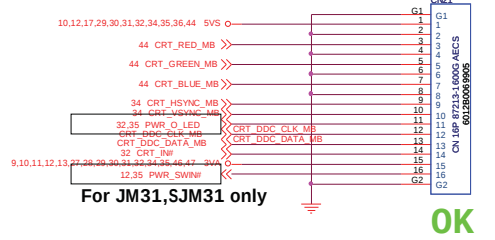




For All Model

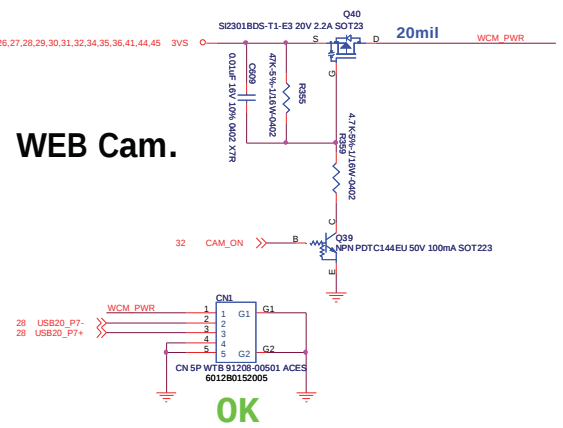
VGA Board CN

(CRT+ PWR SW)



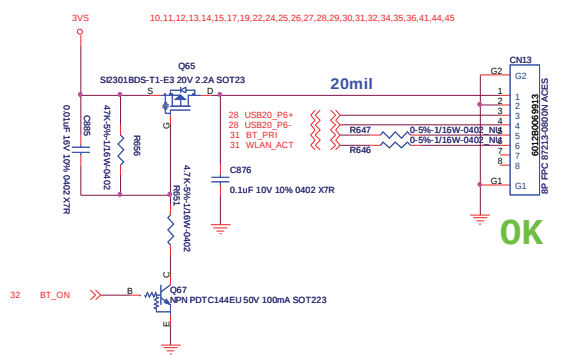
For All Model

WEB Cam.



For All Model

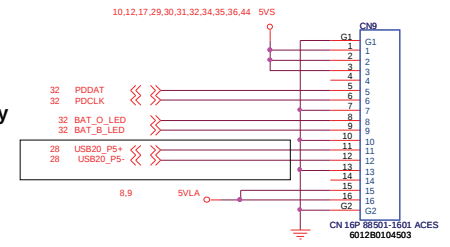
Bluetooth CON.



For All Model

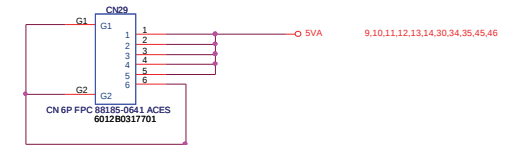
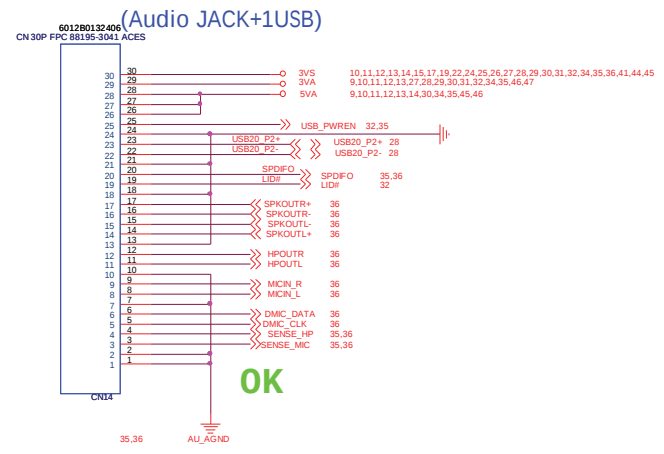
GLIDE PAD Board

For BAP31 only



For All Model

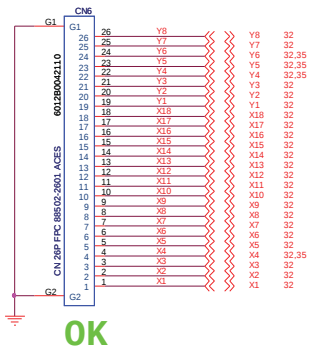
AUDIO Board CN



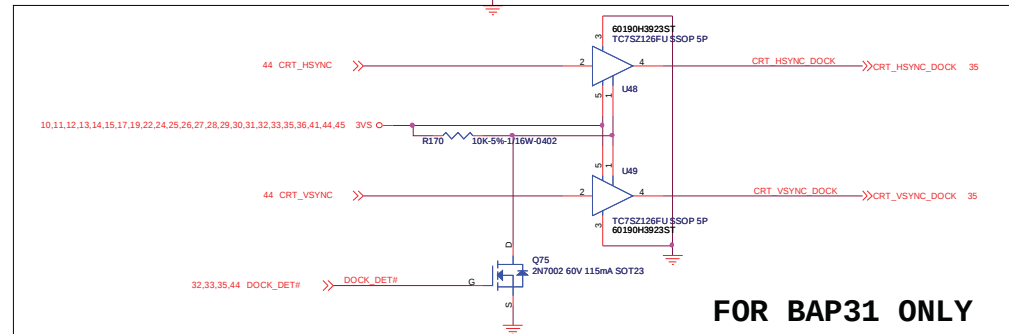
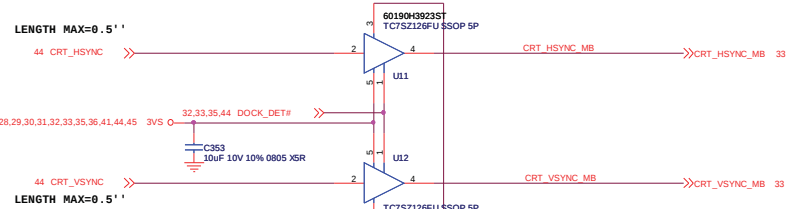
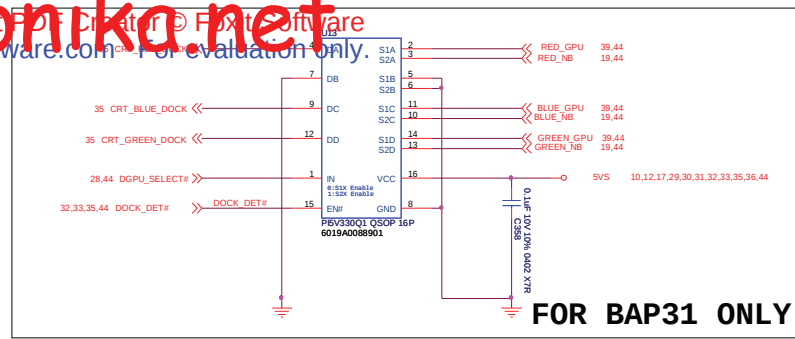
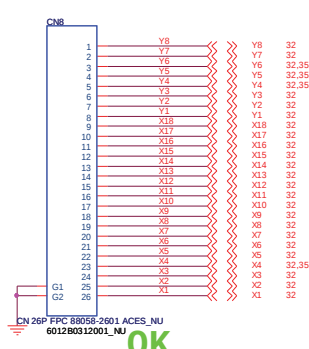
INVENTEC
BAP31G SFF
Daughter Connector

SIZE	CODE	DOC NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET		33	47

To K/B(For All Model)



To K/B(No Use)



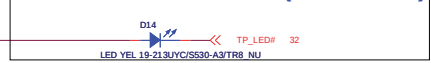
GP lock Button / LED(FOR SJM31)



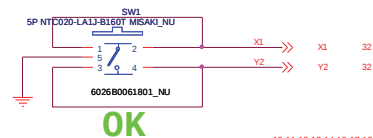
GP lock Button / LED(FOR BAP31)



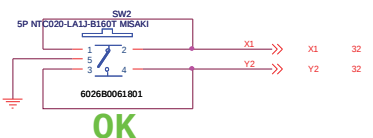
GP lock Button / LED(FOR JM31)



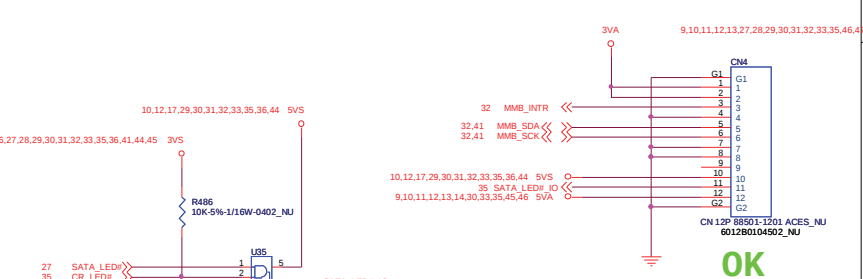
SW (No Use)



SW (FOR All Model)



SW Sensor BOARD(For JM31,SJM31)



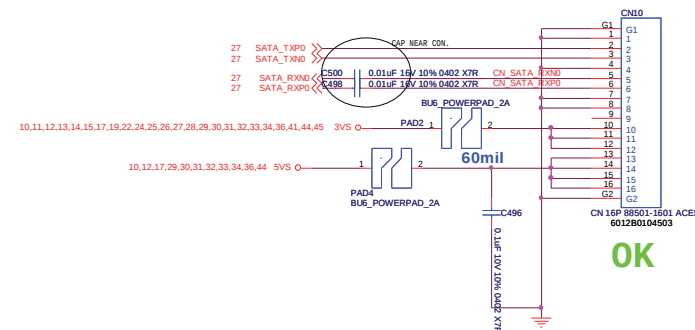
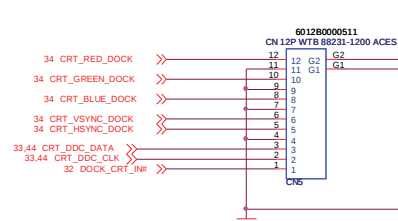
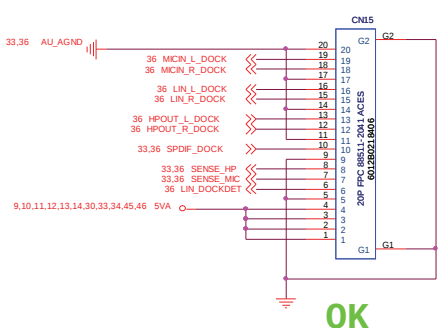
INVENTEC

TITLE			
BAP31G SEF			
BAP			
SIZE	CODE	DOC NUMBER	REV
Custom	CS	D-CS-13/0A226501-ALG	A03
SHEET			
34			

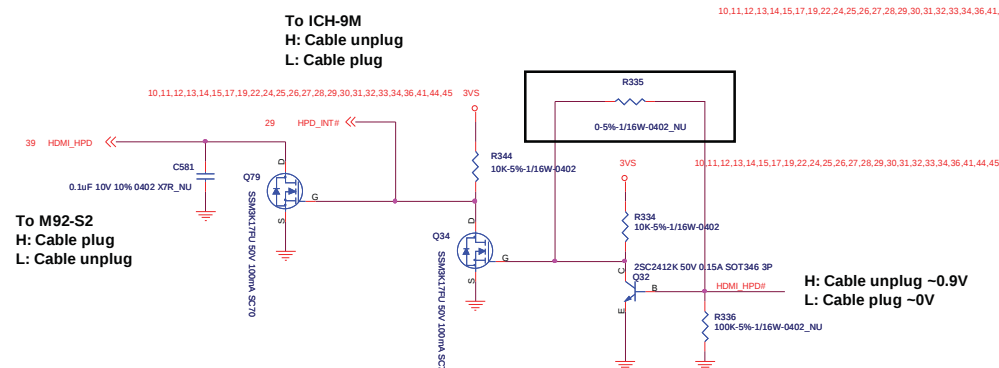
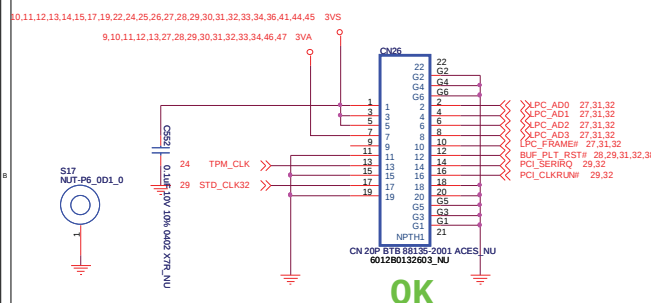
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MB(RGB) TO EASY/B

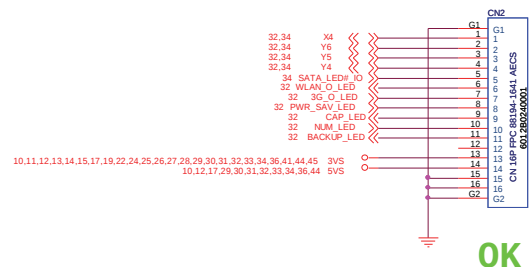
For BAP31



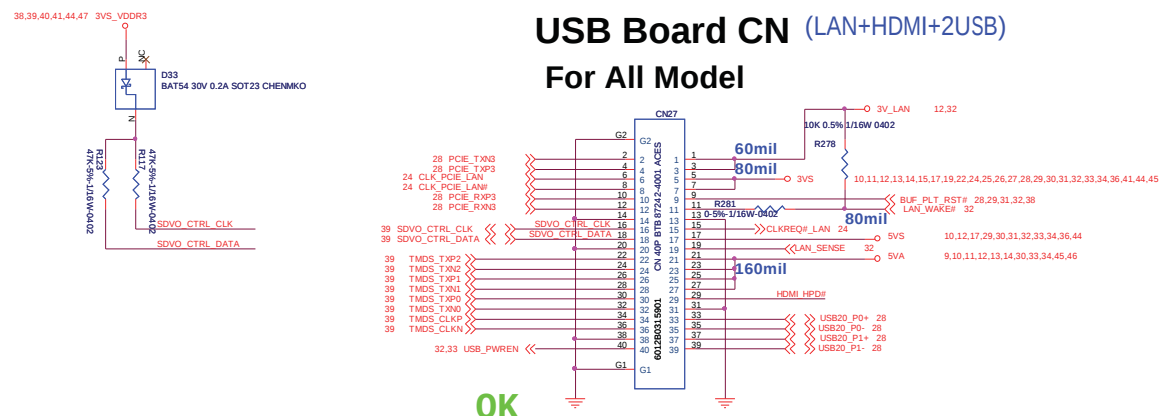
TPM CN



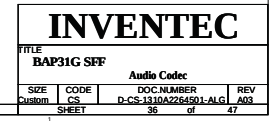
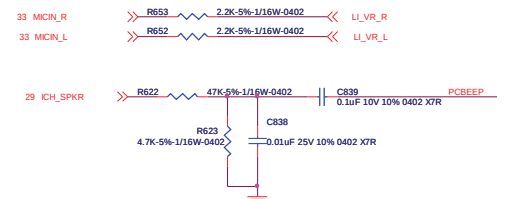
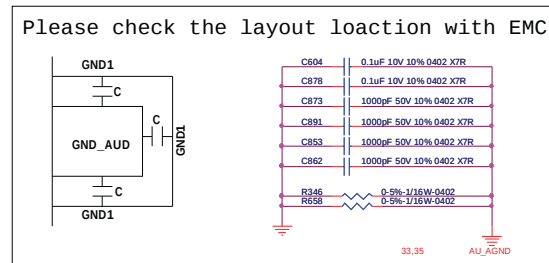
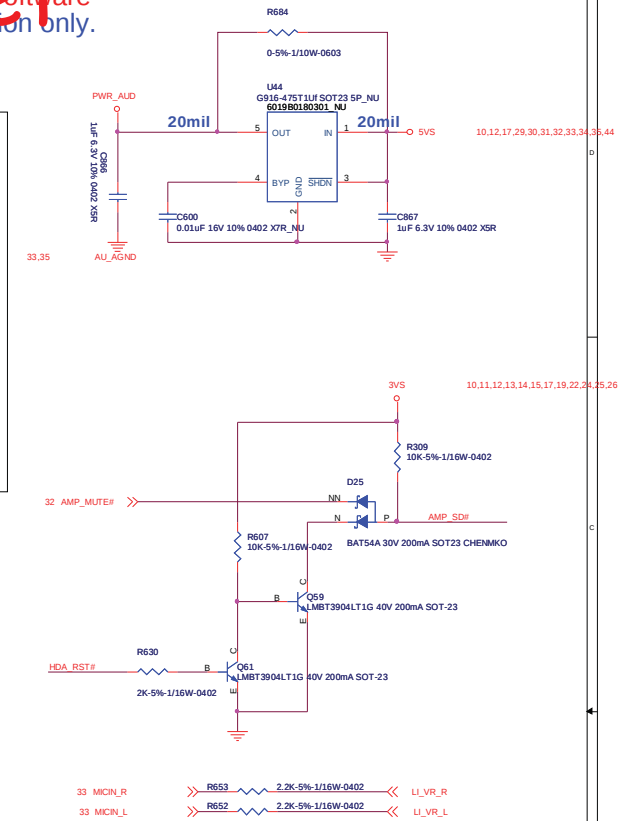
SW/B CN



USB Board CN (LAN+HDMI+2USB)
For All Model



INVENTEC			
TITLE BAP31G SFF			
BDP			
SIZE Custom	CODE CS	DOC NUMBER D-CS-1310A2264501-ALG	REV A03

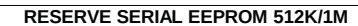
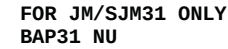
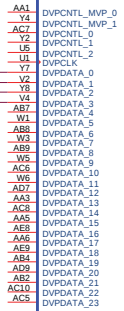
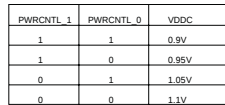


BLANK

INVENTEC				
TITLE BAP31G SFF				
BLANK				
SIZE	CODE	DOC NUMBER	REV	
Custom	CS	D-CS-1310A2264501-ALG	A03	

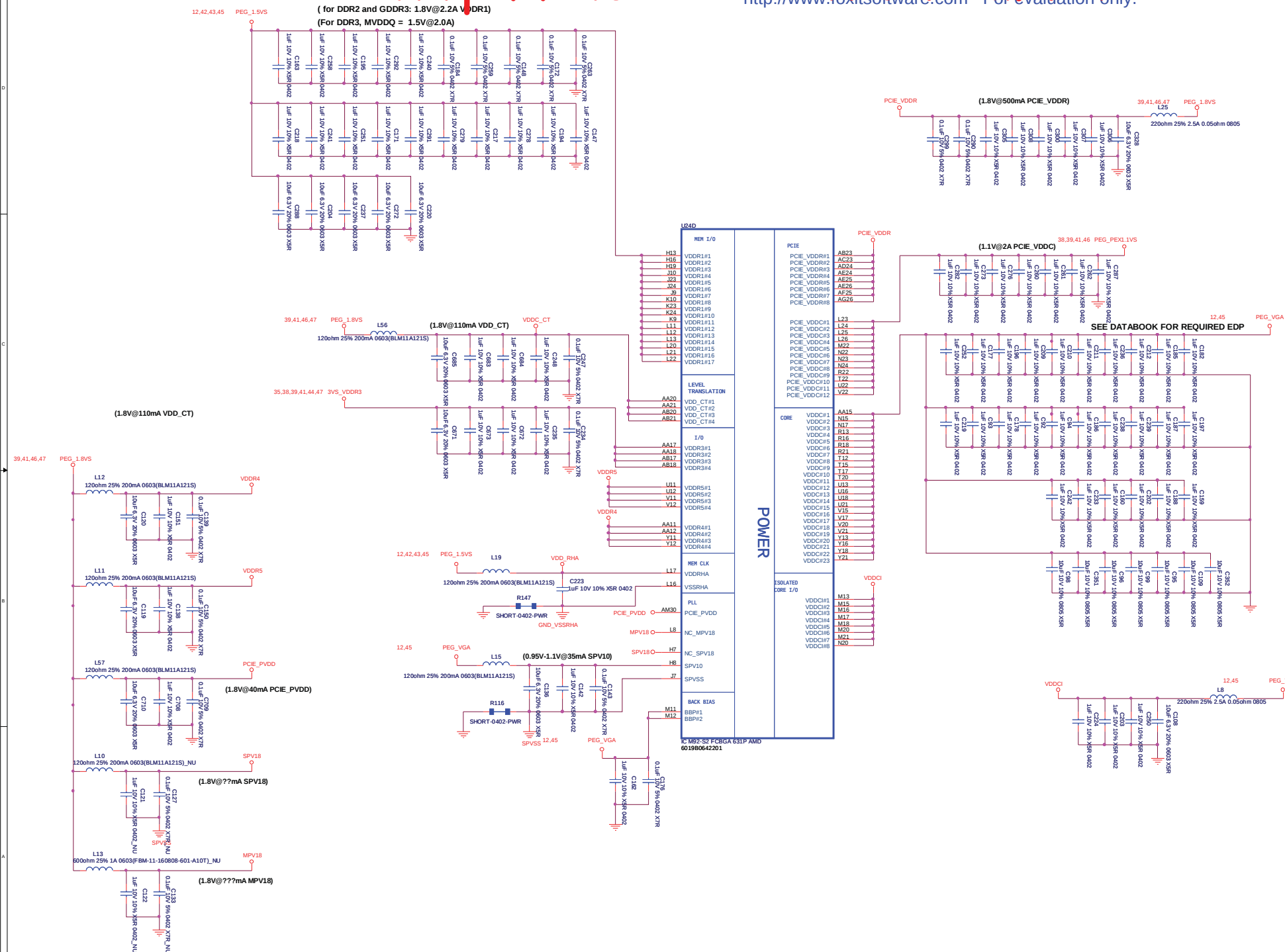


MEM ID3	MEM ID2	MEM ID1	MEM ID0	VENDOR
0	0	0	0	Hynix 64Mx16
1	0	0	0	Samsung 64Mx16

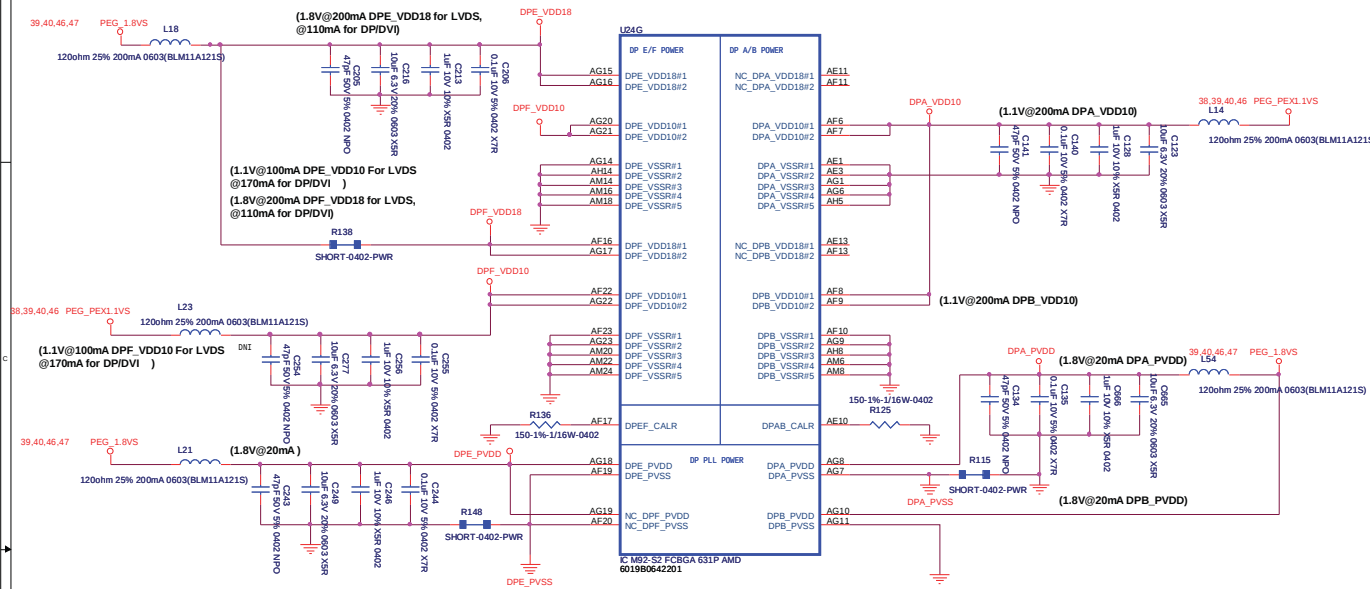


TITLE
BAP31G SFF
M92 [2/5]

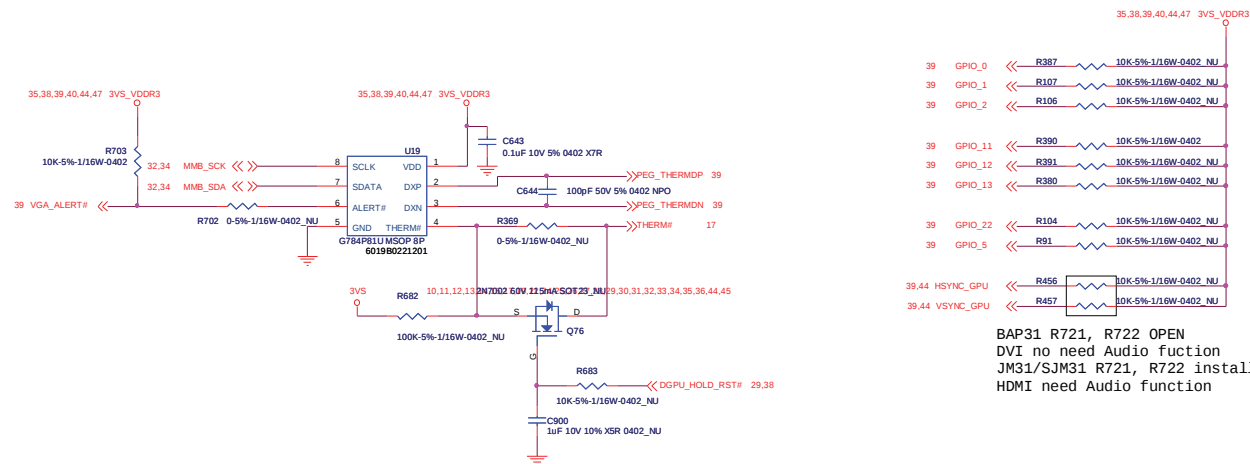
SIZE Custom	CODE CS	DOC NUMBER D-CS-1310A2264501-ALG	REV A03
SHEET		39 of	47



For 92, DPx_VDD10 = 1.1V
For Future ASIC, DPx_VDD10 = 1.0V



PIN STRAPS



CONFIGURATION STRAPS

ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOS ARE USED, THEY MUST NOT CONFLICT DURING RESET

STRAPS	PIN	DESCRIPTION OF DEFAULT SETTINGS	
TX_PWRS_ENB	GPIO0	PCIE FULL TX OUTPUT SWING	X
TX_DEEMPH_EN	GPIO1	PCIE TRANSMITTER DE-EMPHASIS ENABLED	X
BIF_GEN2_EN_A	GPIO2	PCIE GEN2 ENABLED	X
RSVD	GPIO8		0
BIF_VGA_DIS	GPIO9	VGA ENABLED	0
RSVD	GPIO21		0
BIOS_ROM_EN	GPIO_22_ROMCSB	ENABLE EXTERNAL BIOS ROM	X
ROMIDCFG(2:0)	GPIO[13:11]	SERIAL ROM TYPE OR MEMORY APERTURE SIZE SELECT	X X X
VIP_DEVICE_STRAP_ENA	VZSYNC	IGNORE VIP DEVICE STRAPS	X
RSVD	GENERICC		0
AUD[1]	HSYNC	AUD[1] AUD[0]	0
AUD[0]	VSYN	0 0 No audio function 0 1 Audio for DisplayPort and HDMI if dongle is detected 1 0 Audio for DisplayPort only 1 1 Audio for both DisplayPort and HDMI	XX

AMD RESERVED CONFIGURATION STRAPS

ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET

H2SYNC	GENERICC
PULLUP PADS ARE NOT REQUIRED FOR THESE STRAPS BUT IF THESE GPIOS ARE USED, THEY MUST NOT CONFLICT DURING RESET	
GPI021_BB_EN	

INVENTEC

TITLE
BAP31G SFF
M92 [4/5]

SIZE	CODE	DOC. NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET		41	of 47

U24C



LVDS CONTROL		VARY BL DIGON
	TXCLK_UP_DFP3P TXCLK_LN_DFP3N	
	TXOUT_U0P_DFP2P TXOUT_L0N_DFP2N	
	TXOUT_U0P_DFP1P TXOUT_L0N_DFP1N	
	TXOUT_U0P_DFP0P TXOUT_L0N_DFP0N	
	TXOUT_U0P TXOUT_L0N	
LVTRDP		
	TXCLK_L1P_DPE3P TXCLK_L1N_DPE3N	
	TXOUT_L0P_DPE2P TXOUT_L0N_DPE2N	
	TXOUT_L1P_DPE1P TXOUT_L1N_DPE1N	
	TXOUT_L2P_DPE0P TXOUT_L2N_DPE0N	
	TXOUT_L3P TXOUT_L3N	

PLACE MVREF DIVIDERS
AND CAPS CLOSE TO ASIC

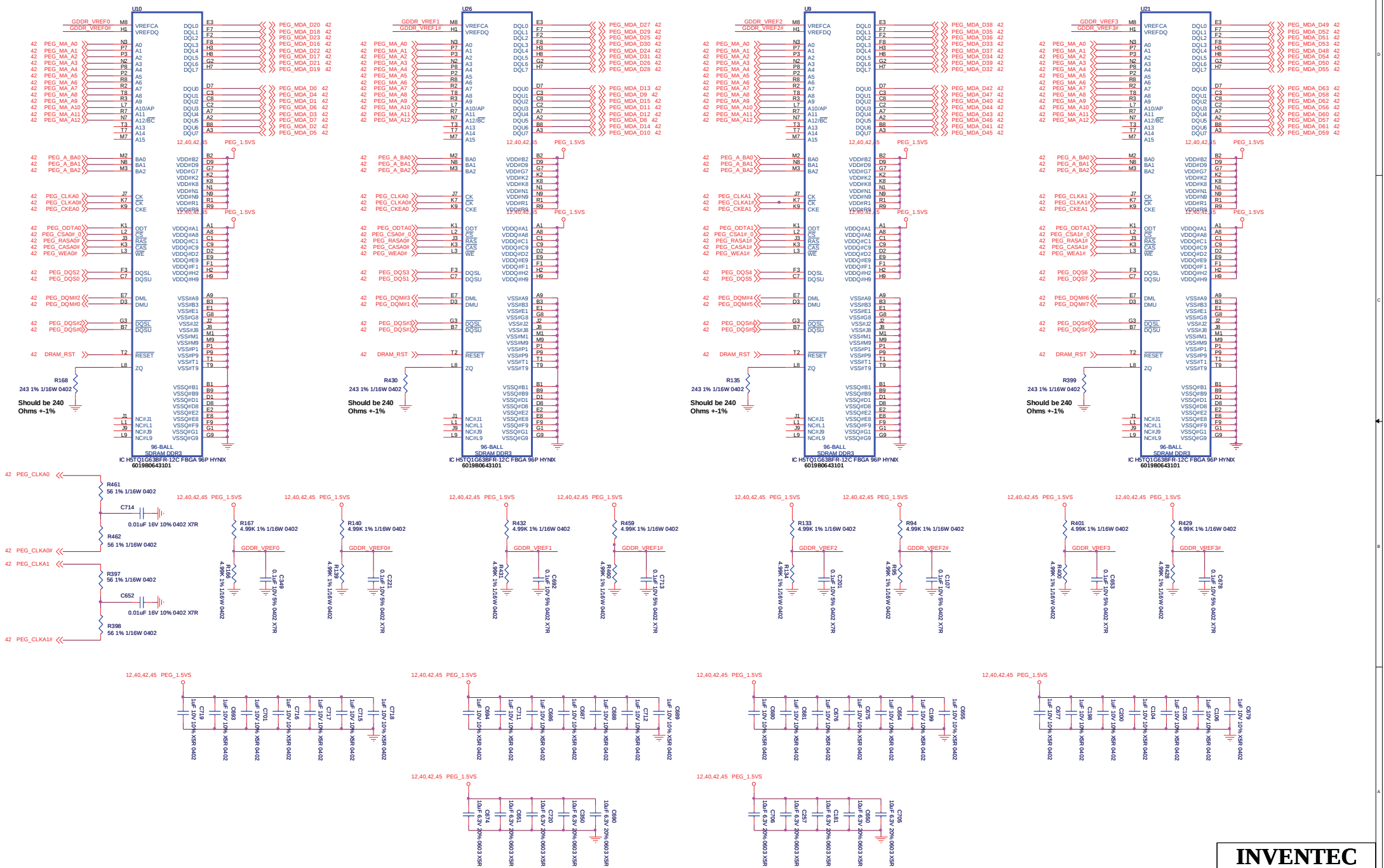
PLACE MVREF DIVIDERS
AND CAPS CLOSE TO ASIC

R110 4.7K-5%-1/16W-0402 R111 4.7K-5%-1/16W-0402

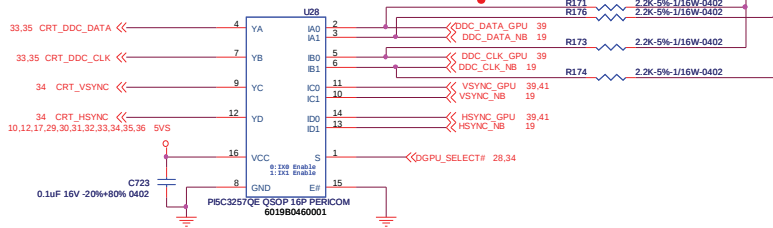
DRAM_RST

TITLE
BAP31G SFF

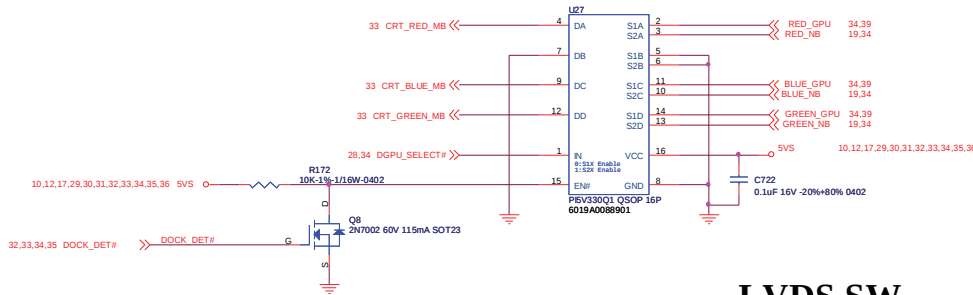
TITLE
BAP31G SFF



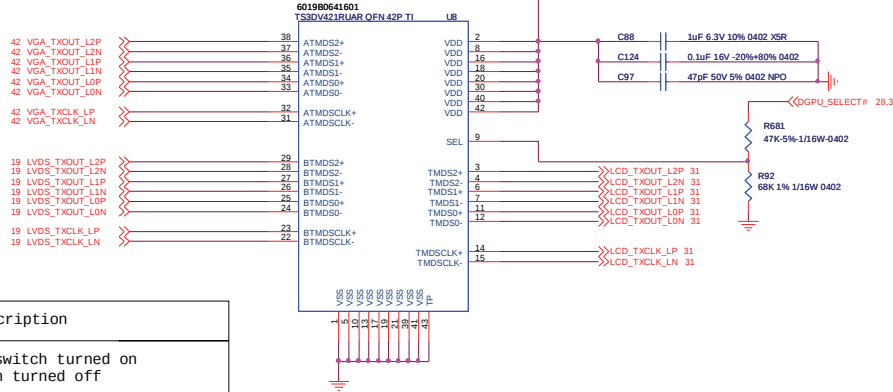
CRT HSYNC/VSYNC/IDC SW



CRT R/G/B SW

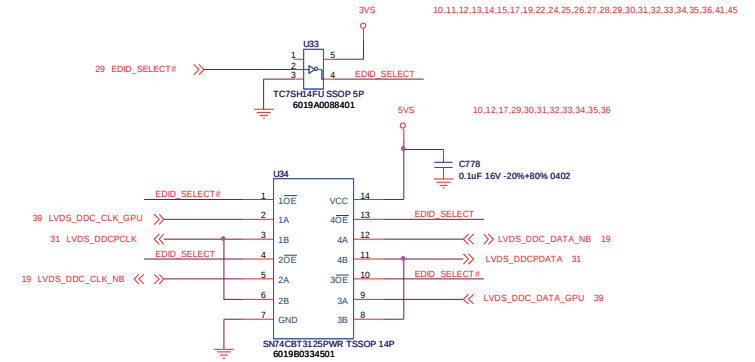


LVDS SW

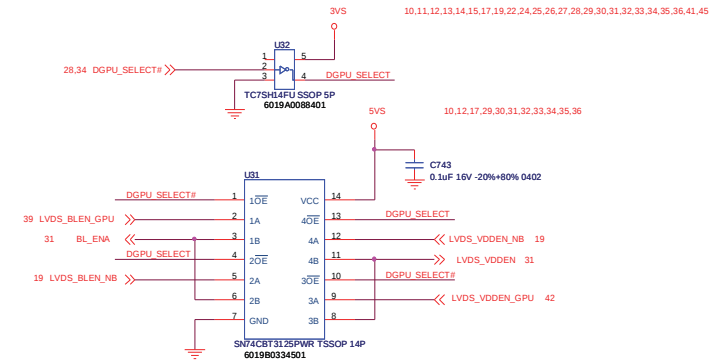


Signal	During Reset	After Reset	Description
DGPU_PWR_EN#	High	High	0 : dGPU power switch turned on 1 : power switch turned off
DGPU_PWROK			0 : dGPU power is not stable 1 : dGPU power is stable
DGPU_HOLD_RST#	Low	Low	0 : Keep dGPU in reset 1 : Reset is released
DGPU_SELECT#	High	High	0 : Display switch enabled for dGPU 1 : Display switch enabled for iGPU
HPD_INT#			0 : DVI insertion 1 : No DVI insertion
PWM_SELECT#		High	0 : PWM switch enabled for dGPU 1 : PWM switch enabled for iGPU
EDID_SELECT#		High	0 : EDID/DDC switch enabled for dGPU 1 : EDID/DDC switch enabled for iGPU

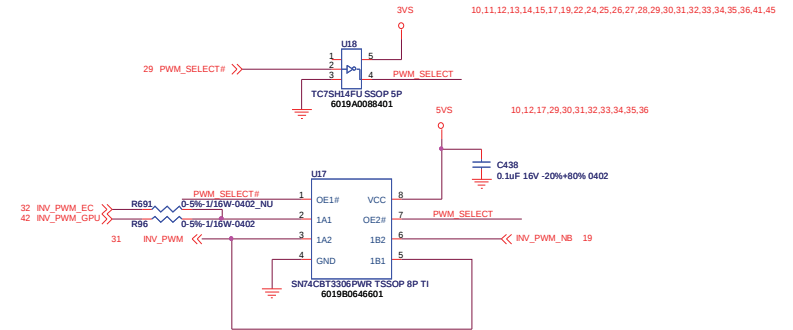
LCD DDC SW



LVDS BKL and Vcc Enable SW



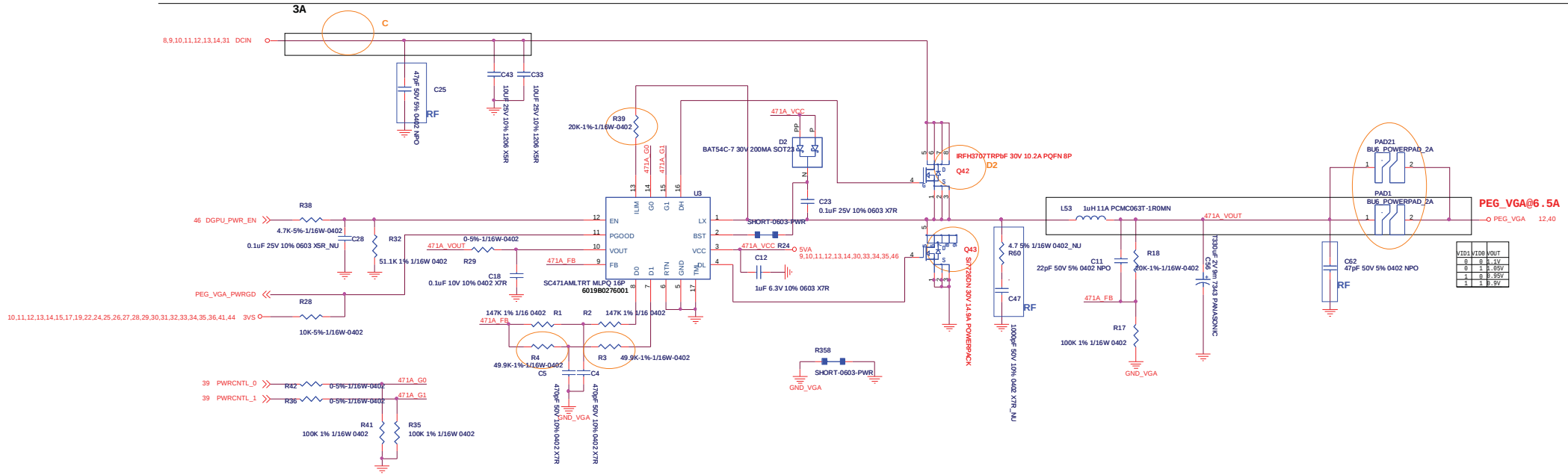
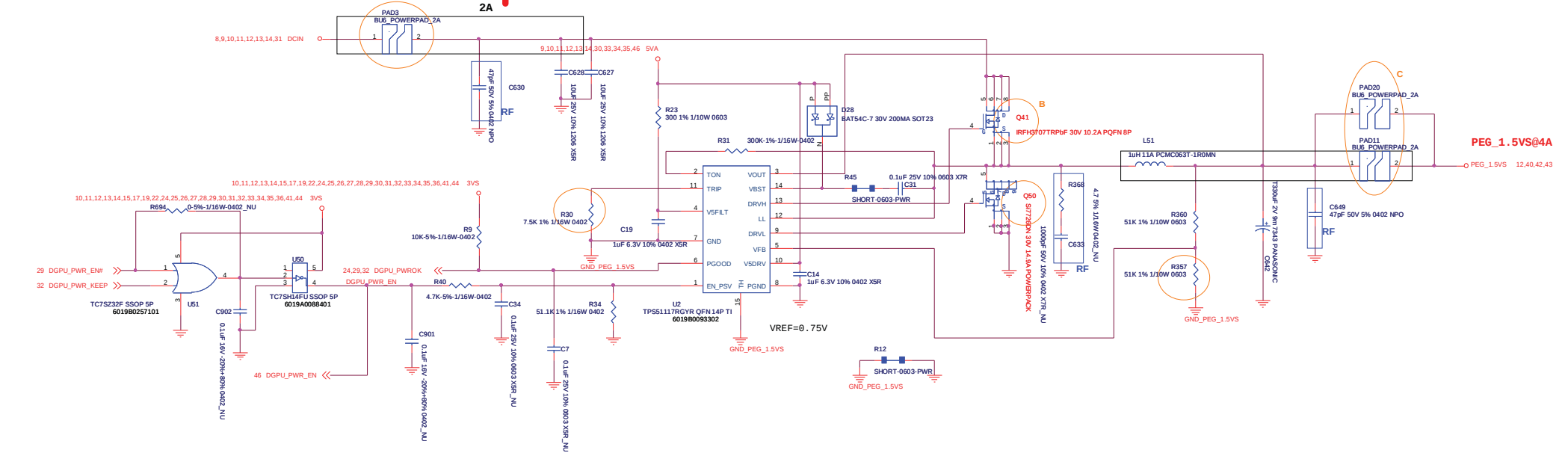
LCD PWM SW



INVENTEC

FILE BAP31G SFF
Hybrid Switch

SIZE	CODE	DOC NUMBER	REV
Custom	CS	D-CS-1310A2264501-ALG	A03
SHEET	44	of	47



PWRCNTL_1	PWRCNTL_0	VDDC
1	1	0.9V
1	0	0.95V
0	1	1.05V
0	0	1.1V

